DACx0508 オクタル、16、14、12ビット、SPI、内部基準電圧搭載の電圧出力DAC

1 特長

- **性能**
  - INL: 16ビット分解能で最大±1LSB
  - TUE: FSRの±0.1% (最大値)
- **2.5Vの高精度内部基準電圧を搭載**
  - 初期精度: ±5mV (最大値)
  - 低ドリフト: 2ppm/℃ (標準値、DAC80508)
- **高い駆動能力: 電源レールから0.5Vで20mA**
- **柔軟な出力構成**
  - ユーザーがゲインを選択可能: 2、1、½
  - ゼロ・スケールまたは中間スケールにリセット
  - 明確な出力機能: DACx0508C
- **広い動作範囲**
  - 電源: 2.7V～5.5V
  - 温度範囲: -40℃～+125℃
- **50MHz SPI互換のシリアル・インターフェイス**
  - 1.7V～5.5Vでの動作
  - デイジー・チェーン動作
  - CRCエラー・チェック
- **低消費電力: 5.5Vで0.6mA/チャネル**
- **小型のパッケージ**
  - 3mm×3mm、16ピンWQFN
  - 2.4mm×2.4mm、16ピンDSBGA

2 アプリケーション

- 光学ネットワーク機器
- ワイヤレス・インフラ
- 産業用オートメーション
- データ収集システム

3 概要

DACx0508は、16、14、12ビットの分解能を持つ、低消費電力、8チャネル、バッファ付き電圧出力のデジタル/アナログ・コンバータ(DAC)のピン互換ファミリです。DACx0508には2.5V、5ppm/℃の内部基準電圧が搭載されているため、ほとんどのアプリケーションでは外付けの高精度基準電圧を必要としません。ユーザーがゲイン構成を選択可能で、フルスケールの出力電圧は1.25V (ゲイン＝½)、2.5V (ゲイン＝1)、または5V (ゲイン＝2)です。このデバイスは2.7V～5.5Vの単電源で動作し、単調性が規定されており、±1 LSB INLの高い線形性を実現します。

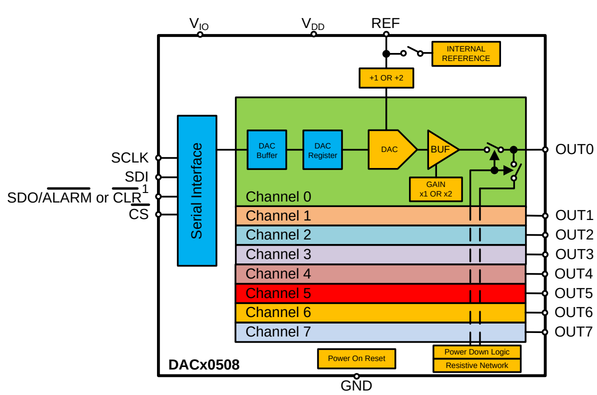
DACx0508への通信はシリアル・インターフェイスで行われ、最高50MHzのクロック速度で動作します。VIOピンにより、1.7V～5.5Vのシリアル・インターフェイス動作が可能です。DACx0508の柔軟なインターフェイスにより、広い範囲の業界標準マイクロプロセッサやマイクロコントローラと動作可能です。

製品情報(1)

型番	パッケージ	本体サイズ(公称)
DACx0508	WQFN (16)	3.00mm×3.00mm
	DSBGA (16)	2.40mm×2.40mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

ブロック概略図



1SDO/ALARM (DACx0508), CLR (DACx0508C)

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4 改訂履歴

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- 「製品情報」にDSBGA (16)パッケージを 追加 ... 1
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5 概要（続き）

DACx0508にはパワー・オン・リセット回路が組み込まれており、DACをパワー・オンしてから、デバイスへ有効なコードが書き込まれるまでDAC出力をゼロ・スケールまたは中間スケールに維持します。このデバイスは、5.5Vにおいて0.6mA/チャネルの低消費電流で動作するため、バッテリで動作する機器に適しています。チャネルごとのパワーダウン機能により、デバイスの消費電流は15μAに低下します。

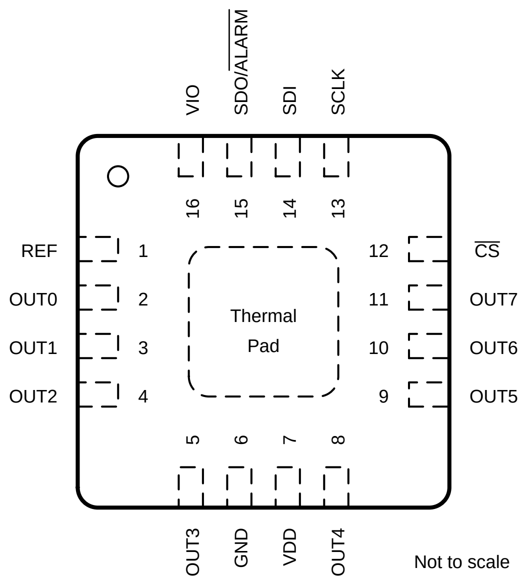
DACx0508は-40℃～+125℃の温度範囲で動作が規定されており、小型のパッケージで供給されます。

6 Device Comparison Table

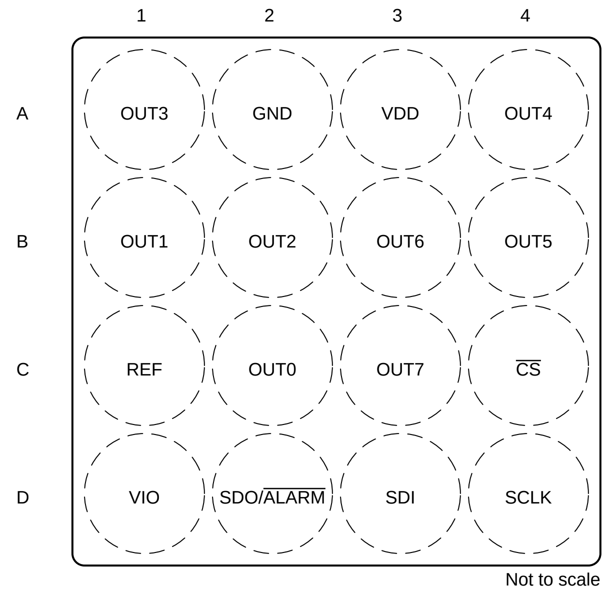
DEVICE	RESOLUTION	REFERENCE	RESET	SDO OR $\overline{CLR}$ OPERATION
DAC80508Z	16-Bit	Internal (default) / External	Zero	SDO
DAC80508ZC				$\overline{CLR}$
DAC80508M			Midscale	SDO
DAC80508MC				$\overline{CLR}$
DAC70508Z	14-Bit	Internal (default) / External	Zero	SDO
DAC70508M			Midscale	SDO
DAC60508Z	12-Bit	Internal (default) / External	Zero	SDO
DAC60508ZC				$\overline{CLR}$
DAC60508M			Midscale	SDO
DAC60508MC				$\overline{CLR}$

7 Pin Configuration and Functions

RTE Package
16-Pin WQFN
Top View



YZF Package
16-Pin DSBGA
Top View



Pin Functions

PIN			TYPE	DESCRIPTION
NAME	WQFN NO.	DSBGA NO.		
REF	1	C1	I/O	When using internal reference, this is the reference output voltage pin (default). When using an external reference, this is the reference input pin to the device.
OUT0	2	C2	O	Analog output voltage from DAC 0.
OUT1	3	B1	O	Analog output voltage from DAC 1.
OUT2	4	B2	O	Analog output voltage from DAC 2.
OUT3	5	A1	O	Analog output voltage from DAC 3.
GND	6	A2	GND	Ground reference point for all circuitry on the device.
VDD	7	A3	PWR	Analog supply voltage (2.7 V to 5.5 V).
OUT4	8	A4	O	Analog output voltage from DAC 4.
OUT5	9	B4	O	Analog output voltage from DAC 5.
OUT6	10	B3	O	Analog output voltage from DAC 6.
OUT7	11	C3	O	Analog output voltage from DAC 7.
$\overline{CS}$	12	C4	I	Active low serial data enable. This input is the frame synchronization signal for the serial data. When the signal goes low, it enables the serial interface input shift register.
SCLK	13	D4	I	Serial interface clock.
SDI	14	D3	I	Serial interface data input. Data are clocked into the input shift register on each falling edge of the SCLK pin.
SDO/$\overline{ALARM}$	15	D2	O	DACx0508. Serial interface data output (default). The SDO pin is in high impedance when $\overline{CS}$ pin is high. Data are clocked out of the input shift register on either rising or falling edges of the SCLK pin as specified by the FSDO bit. Alternatively the pin can be configured as an $\overline{ALARM}$ open-drain output to indicate a CRC or reference alarm event. If configured as $\overline{ALARM}$ a 10 kΩ, pull-up resistor to V_{IO} is required.
$\overline{CLR}$			I	DACx0508C. A low value on the $\overline{CLR}$ pin causes the DAC outputs of those channels configured for clear operation to update their registers and output to the reset value: zero scale (DACx0508Z) or midscale (DACx0508M). Bringing the $\overline{CLR}$ pin high causes the device to exit clear mode.

Pin Functions (continued)

PIN			TYPE	DESCRIPTION
NAME	WQFN NO.	DSBGA NO.		
VIO	16	D1	PWR	IO supply voltage (1.7 V to 5.5 V). This pin sets the I/O operating voltage for the serial interface.
Thermal Pad	–	–	–	The thermal pad is located on the bottom-side of the WQFN package. The thermal pad should be connected to any internal PCB ground plane using multiple vias for good thermal performance.

8 Specifications

8.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
Suppy voltage	V_{DD} to GND	–0.3	6	V
	V_{IO} to GND	–0.3	6	
Pin voltage	DAC outputs to GND	–0.3	V_{DD} + 0.3	V
	REF to GND	–0.3	V_{DD} + 0.3	
	Digital pins to GND	–0.3	V_{IO} + 0.3	
Input current	Input current to any pin except supply pins	–10	10	mA
Temperature	Operating free-air, T_A	-40	125	°C
	Junction, T_J	–40	150	
	Storage, T_{stg}	–60	150	

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

8.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per JEDEC Standard 22 Test Method A114-C.01 (1)	±3000	V
		Charged-device model (CDM), per JEDEC Standard 22 Test Method C101, all pins (2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

8.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
POWER SUPPLY						
V_{DD}	Analog supply voltage		2.7		5.5	V
V_{IO}	IO supply voltage		1.7		5.5	
DIGITAL INPUTS						
	Digital input voltage		0		V_{IO}	V
REFERENCE INPUT						
V_{REFIN}	V_{DD} = 2.7 V to 3.3 V	Reference divider disabled	1.2		$(V_{DD} – 0.2)/2$	V
		Reference divider enabled	2.4		$V_{DD} – 0.2$	
	V_{DD} = 3.3 V to 5.5 V	Reference divider disabled	1.2		$V_{DD}/2$	
		Reference divider enabled	2.4		V_{DD}	
TEMPERATURE						
T_A	Operating free-air temperature		–40		125	°C

8.4 Thermal Information

THERMAL METRIC(1)		DACx0508 RTE (WQFN) 16 PINS	DACx0508 YZF (DSBGA) 16 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	33.3	68.0	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	29.5	0.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	7.3	16.9	°C/W
ψ_{JT}	Junction-to-top characterization parameter	0.2	0.2	°C/W
ψ_{JB}	Junction-to-board characterization parameter	7.4	16.9	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	0.9	n/a	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

8.5 Electrical Characteristics

All minimum and maximum specifications at V_{DD}= 2.7 V to 5.5 V, V_{IO} = 1.7 V to 5.5 V, V_{REFIN} = 1.25 V to 5.5 V, R_{LOAD} = 2 kΩ to GND, C_{LOAD} = 200 pF to GND, digital inputs at V_{IO} or GND, T_A = –40°C to 125°C (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC PERFORMANCE(1)						
	Resolution	DAC80508	16			Bits
		DAC70508	14			
		DAC60508	12			
INL	Integral nonlinearity	DAC80508		±0.5	±1	LSB
		DAC70508		±0.5	±1	
		DAC60508		±0.5	±1	
DNL	Differential nonlinearity	DAC80508. Specified 16-bit monotonic		±0.5	±1	LSB
		DAC70508. Specified 14-bit monotonic		±0.5	±1	
		DAC60508. Specified 12-bit monotonic		±0.5	±1	
TUE	Total unadjusted error	DAC80508. All Gains		±0.05	±0.1	%FSR
		DAC70508 and DAC60508. Gain = 1 and Gain = 2		±0.06	±0.14	
		DAC70508 and DAC60508. Gain = ½		±0.1	±0.2	
	Offset error	DAC80508. WQFN and BGA packages. All gains.		±0.75	±1.5	mV
		DAC70508 and DAC60508. WQFN package: Gain = 1, Gain = 2 and Gain = ½. DSBGA package: Gain = 2		±0.75	±1.5	
		DAC70508 and DAC60508. DSBGA package: Gain = 1 and Gain = ½		±0.75	±2.5	
	Zero-code error	DAC code = zero scale		0.5	1.5	mV
	Full-scale error	DAC80508. All gains		±0.05	±0.1	% FSR
		DAC70508 and DAC60508. Gain = 1 and Gain = 2		±0.075	±0.14	
		DAC70508 and DAC60508. Gain = ½		±0.1	±0.22	
	Gain error	DAC80508		±0.05	±0.1	% FSR
		DAC70508 and DAC60508		±0.05	±0.14	
	Offset error drift			±1		µV/°C
	Zero-code error drift			±2		µV/°C
	Full-scale error drift			±2		ppm of FSR/°C
	Gain error drift			±1		ppm of FSR/°C
	Output voltage drift over time	T_A = 25°C, DAC code = midscale, 1600 hours		20		ppm of FSR

(1) Static performance specified with DAC outputs unloaded for all gain options, unless otherwise noted. End point fit between codes. 16-bit: Code 256 to 65280, 14-bit: Code 128 to 16127, 12-bit: Code 16 to 4031

Electrical Characteristics (continued)

All minimum and maximum specifications at V_{DD}= 2.7 V to 5.5 V, V_{IO} = 1.7 V to 5.5 V, V_{REFIN} = 1.25 V to 5.5 V, R_{LOAD} = 2 kΩ to GND, C_{LOAD} = 200 pF to GND, digital inputs at V_{IO} or GND, T_A = –40°C to 125°C (unless otherwise noted).

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OUTPUT CHARACTERISTICS					
Voltage range	Gain = 2 (BUFF-GAIN = 1, REF-DIV = 0)	0		2 × V_{REF}	V
	Gain = 1 (BUFF-GAIN = 1, REF-DIV = 1)	0		V_{REF}	
	Gain = ½ (BUFF-GAIN = 0, REF-DIV = 1)	0		½ × V_{REF}	
Output voltage headroom	to GND or V_{DD} (unloaded)		0.004		V
	to GND or V_{DD} (-5 mA ≤ I_{OUT} ≤ 5 mA)	0.15			
	to GND or V_{DD} (-10 mA ≤ I_{OUT} ≤ 10 mA)	0.3			
	to GND or V_{DD} (-20 mA ≤ I_{OUT} ≤ 20 mA)	0.5			
Short circuit current[(2)]	DAC code = full scale. Output shorted to GND		30		mA
	DAC code = zero scale. Output shorted to V_{DD}		35		
Load regulation	DAC code = midscale, -10 mA ≤ I_{OUT} ≤ 10 mA		85		µV/mA
Maximum capacitive load[(3)]	R_{LOAD} = ∞	0		2	nF
	R_{LOAD} = 2 kΩ	0		10	
DC output impedance	DAC code = midscale		0.085		Ω
	DAC output at GND or V_{DD}		15		
DYNAMIC PERFORMANCE					
Output voltage settling time	¼ to ¾ scale and ¾ to ¼ scale settling time to ±2 LSB, V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 2		5		µs
Slew rate	V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 2		1.8		V/µs
Power-up time	DAC*x*-PWDWN 1 to 0 transition. DAC code = full scale. V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 2[(4)]		12		µs
Power-up glitch magnitude	DAC code = zero scale. V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 2. C_{LOAD} = 50 pF		25		mV
Output noise	0.1 Hz to 10 Hz, DAC code = midscale, V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 2		14		µVpp
Output noise density	1 kHz, DAC code = midscale, V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 2		78		nV/√Hz
	10 kHz, DAC code = midscale, V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 2		74		
	1 kHz, DAC code = full scale, V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 1		55		
	10 kHz, DAC code = full scale, V_{DD} = 5.5 V, V_{REFIN} = 2.5 V, Gain = 1		50		
AC PSRR	DAC code = midscale, frequency = 60 Hz, amplitude = 200 mV_{PP} superimposed on V_{DD}		85		dB
DC PSRR	DAC code = midscale, V_{DD} = 5 V ± 10%		10		µV/V
Code change glitch impulse	1 LSB change around major carrier		4		nV-s
Channel to Channel AC crosstalk	DAC code = midscale. Code 32 to full-scale swing on adjacent channel		0.2		nV-s
Channel to Channel DC crosstalk	DAC80508. Measured channel at midscale. Adjacent channel at full scale		5		µV
	DAC70508 and DAC60508. Measured channel at midscale. Adjacent channel at full scale		10		
	DAC80508. Measured channel at midscale. All other channels at full scale		10		
	DAC70508 and DAC60508. Measured channel at midscale. All other channels at full scale		80		
Digital feedthrough	DAC code = midscale. f_{SCLK} = 1 MHz, SDO disabled		0.1		nV-s
EXTERNAL REFERENCE INPUT					
Reference input current	V_{REFIN} = 2.5 V		25		µA
Reference input impedance			100		kΩ
Reference input capacitance			5		pF

(2) Temporary overload condition protection. Junction temperature can be exceeded during current limit. Operation above the specified maximum junction temperature may impair device reliability.
(3) Specified by design and characterization. Not tested during production.
(4) Time to exit DAC power-down mode. Measured from $\overline{CS}$ rising edge to 90% of DAC final value.

Electrical Characteristics (continued)

All minimum and maximum specifications at V_{DD}= 2.7 V to 5.5 V, V_{IO} = 1.7 V to 5.5 V, V_{REFIN} = 1.25 V to 5.5 V, R_{LOAD} = 2 kΩ to GND, C_{LOAD} = 200 pF to GND, digital inputs at V_{IO} or GND, T_A = –40°C to 125°C (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
INTERNAL REFERENCE						
	Reference output voltage, V_{REFOUT}	T_A = 25°C	2.495	2.5	2.505	V
	Reference output drift	DAC80508		2	5	ppm/°C
		DAC70508 and DAC60508		5	8	
	Reference output impedance			0.1		Ω
	Reference output noise	0.1 Hz to 10 Hz		15		μVpp
	Reference output noise density	10 kHz, REF_{LOAD} = 10 nF		130		$nV/\sqrt{Hz}$
	Reference load current			±5		mA
	Reference load regulation	Source and sink		100		μV/mA
	Reference line regulation			20		μV/V
	Reference output drift over time	T_A = 25°C, 1600 hours		4.8		ppm
	Reference thermal hysteresis	DAC80508. First cycle		50		ppm
		DAC70508 and DAC60508. First cycle		190		
		Additional cycle		18		
DIGITAL INPUTS						
V_{IH}	High-level input voltage		0.7 × V_{IO}			V
V_{IL}	Low-level input voltage				0.3 × V_{IO}	V
	Input current			±2		μA
	Input pin capacitance			2		pF
DIGITAL OUTPUTS: SDO/$\overline{\text{ALARM}}$						
V_{OH}	High-level output voltage	I_{LOAD} = 0.2 mA	V_{IO} – 0.4			V
V_{OL}	Low-level output voltage	I_{LOAD} = -0.2 mA			0.4	V
	Output pin capacitance			4		pF
POWER SUPPLY REQUIREMENTS						
I_{DD}	V_{DD} supply current	Active mode. Internal reference enabled. Gain = 1. DAC code = full scale. Outputs unloaded. SPI static		5	6	mA
		Active mode. Internal reference disabled. Gain = 1. DAC code = full scale. Outputs unloaded. SPI static		4.5	5.5	
		Power-down		15		μA
I_{IO}	V_{IO} supply current			2	3	μA

8.6 Typical Characteristics

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.

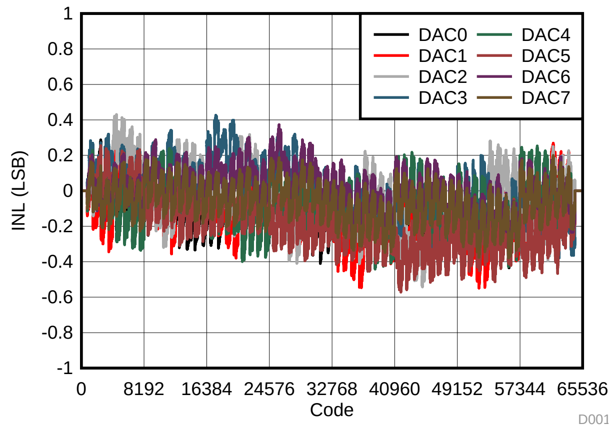


Figure 1. Integral Linearity Error vs Digital Input Code

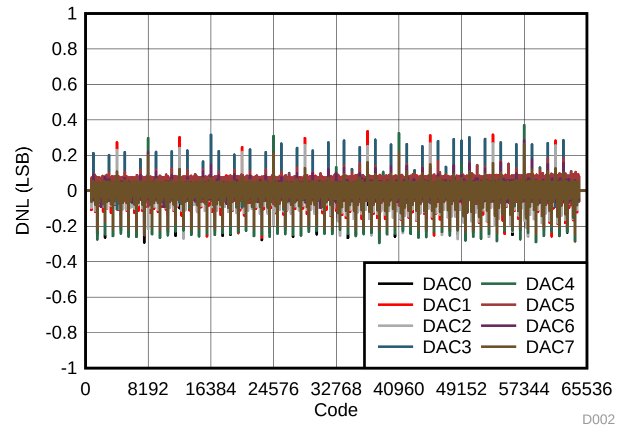


Figure 2. Differential Linearity Error vs Digital Input Code

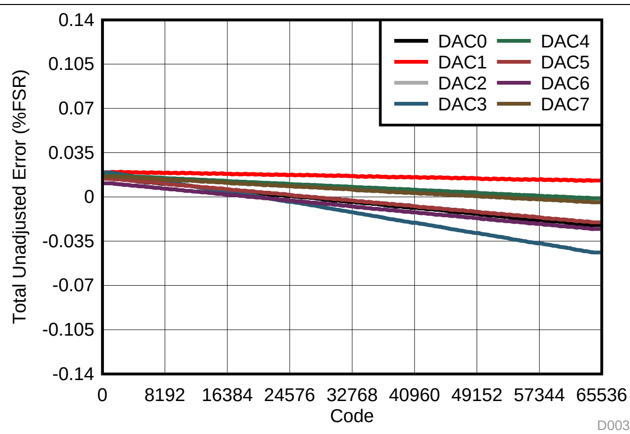


Figure 3. Total Unadjusted Error vs Digital Input Code

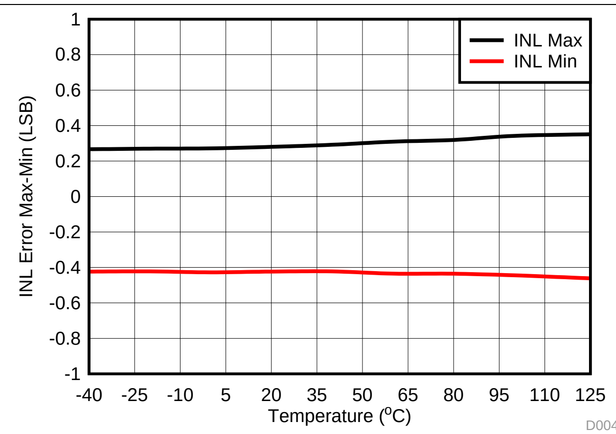


Figure 4. Integral Linearity Error vs Temperature

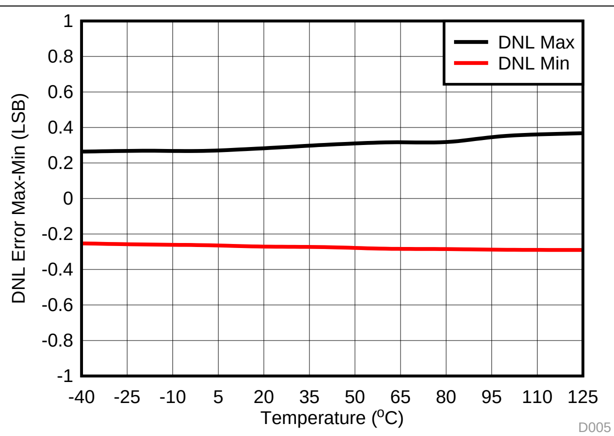


Figure 5. Differential Linearity Error vs Temperature

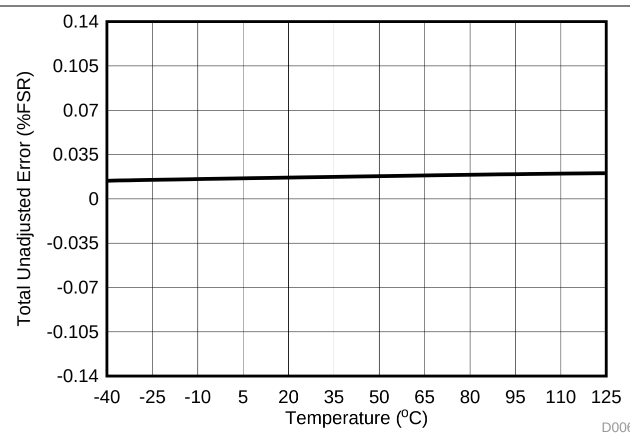


Figure 6. Total Unadjusted Error vs Temperature

Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.

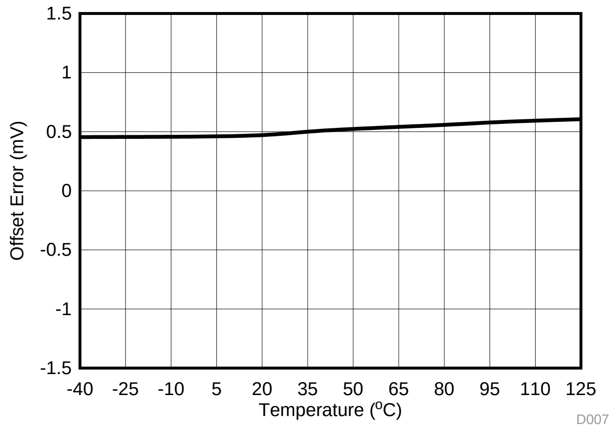


Figure 7. Offset Error vs Temperature

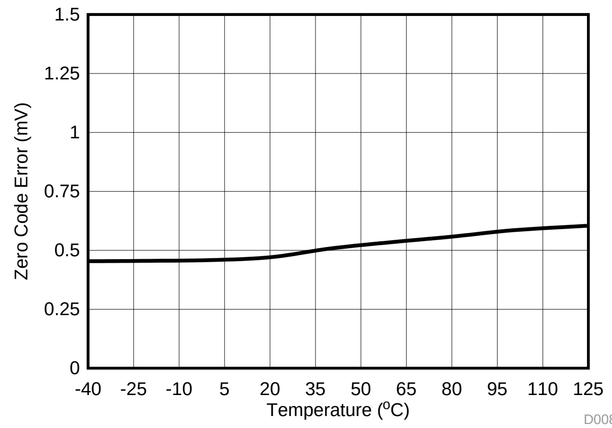


Figure 8. Zero Code Error vs Temperature

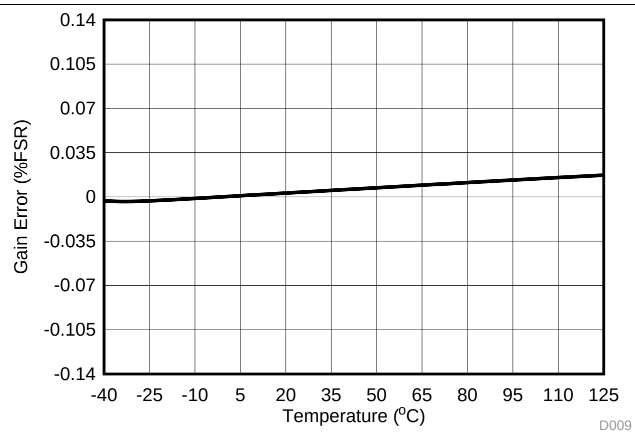


Figure 9. Gain Error vs Temperature

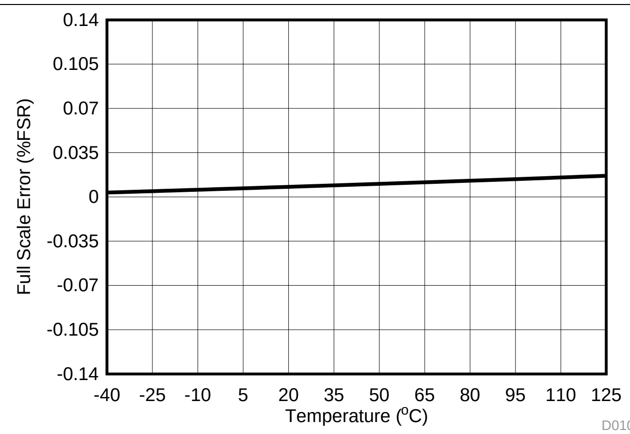
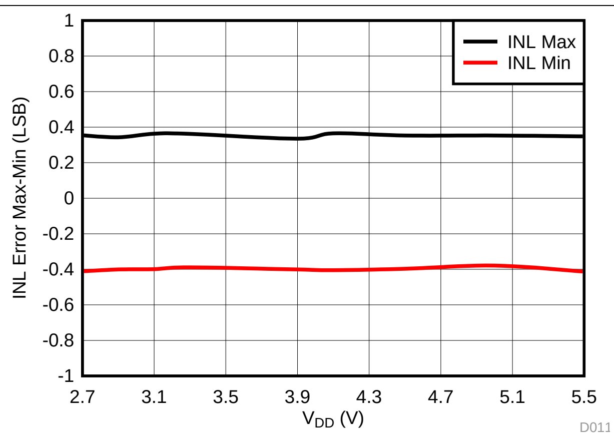
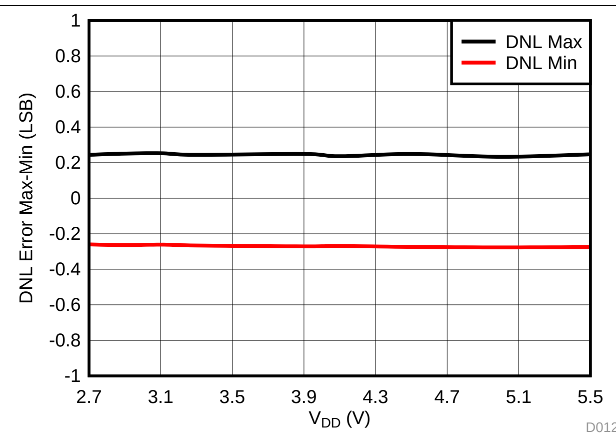


Figure 10. Full Scale Error vs Temperature



Gain = 1

Figure 11. Integral Linearity Error vs Supply Voltage

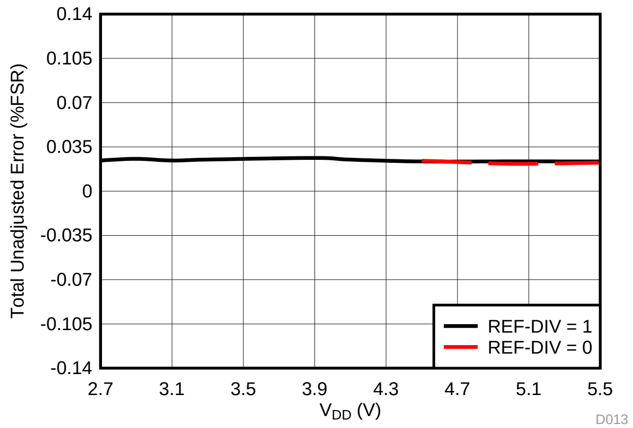


Gain = 1

Figure 12. Differential Linearity Error vs Supply Voltage

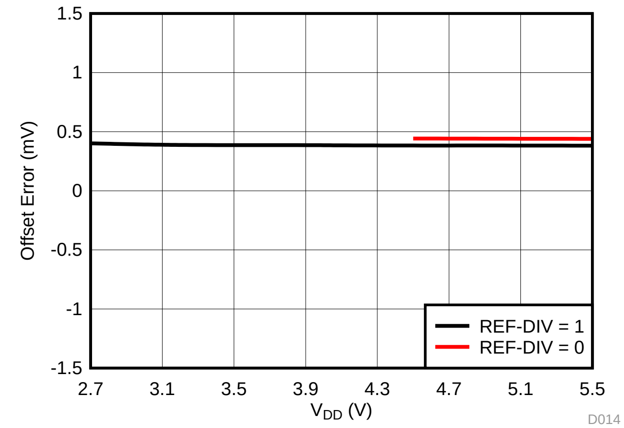
Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.



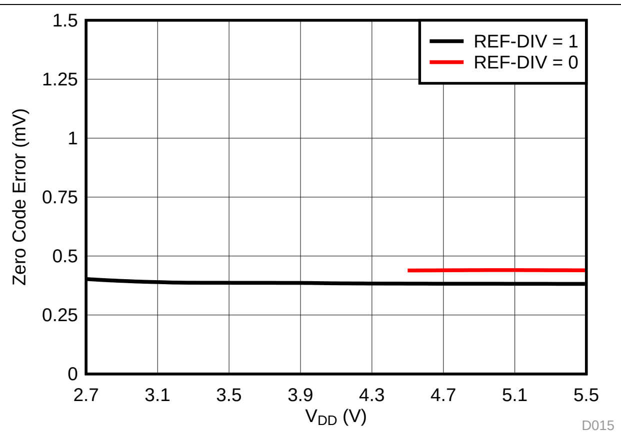
Gain = 1

Figure 13. Total Unadjusted Error vs Supply Voltage



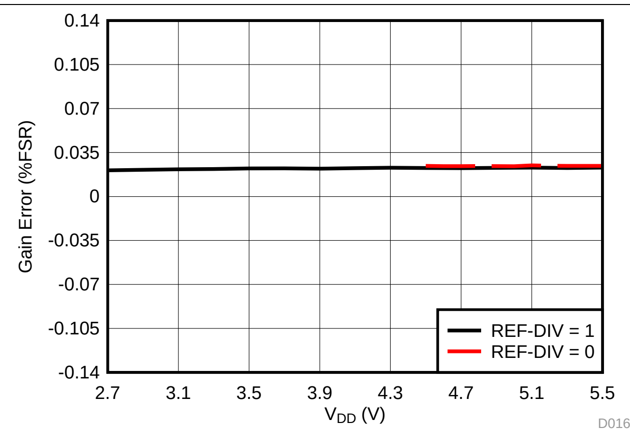
Gain = 1

Figure 14. Offset Error vs Supply Voltage



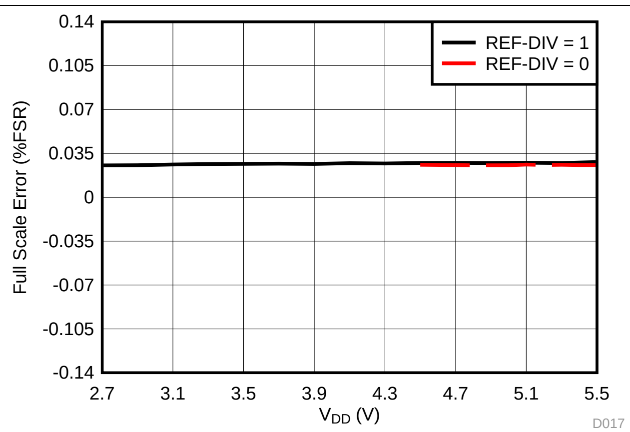
Gain = 1

Figure 15. Zero Code Error vs Supply Voltage



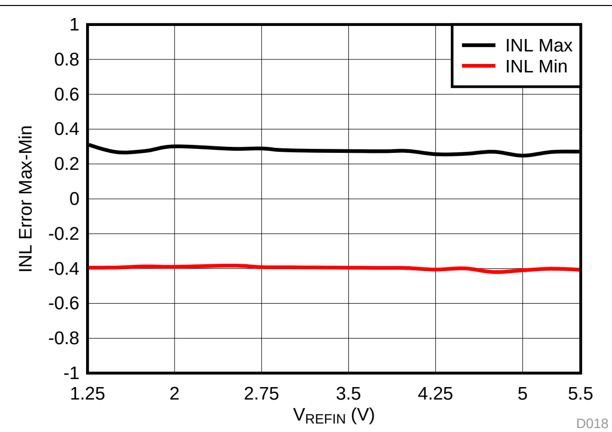
Gain = 1

Figure 16. Gain Error vs Supply Voltage



Gain = 1

Figure 17. Full Scale Error vs Supply Voltage

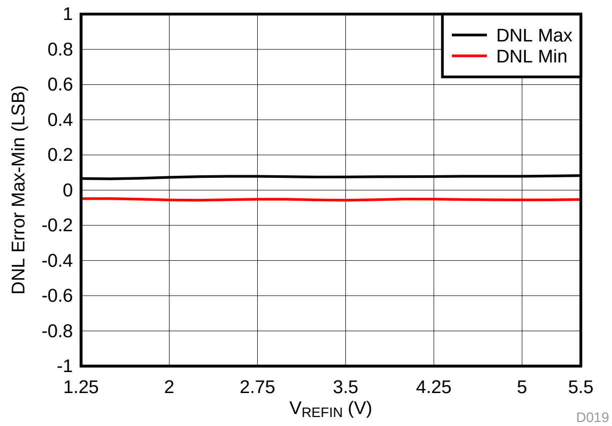


Gain = 1

Figure 18. Integral Linearity Error vs Reference Voltage

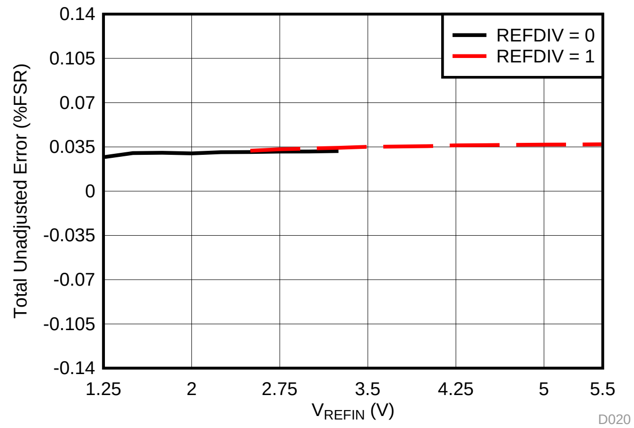
Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.



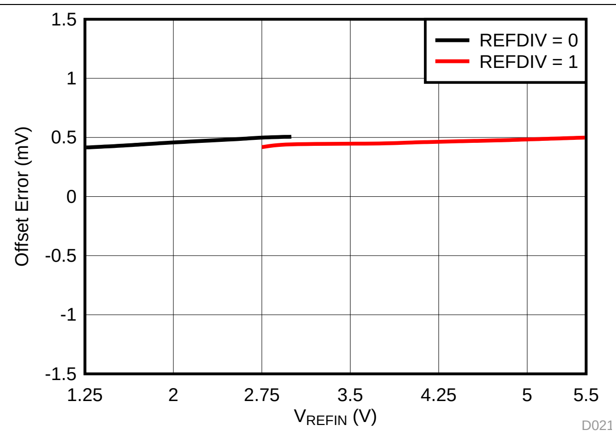
Gain = 1

Figure 19. Differential Linearity Error vs Reference Voltage



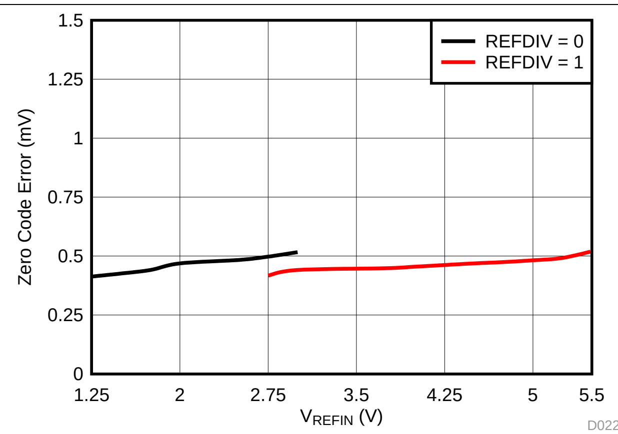
Gain = 1

Figure 20. Total Unadjusted Error vs Reference Voltage



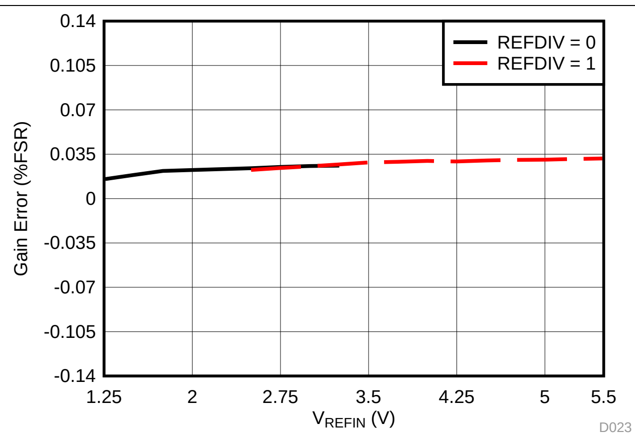
Gain = 1

Figure 21. Offset Error vs Reference Voltage



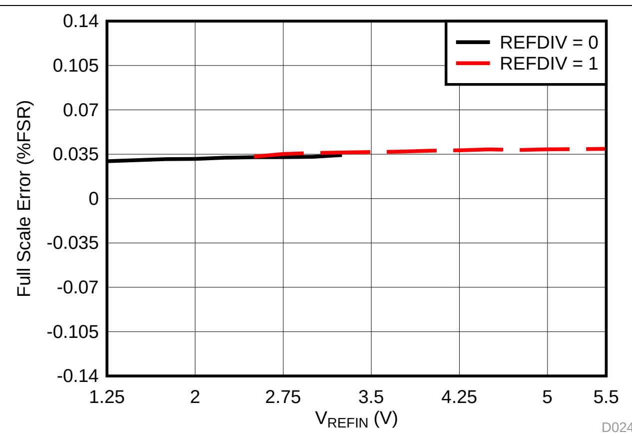
Gain = 1

Figure 22. Zero Code Error vs Reference Voltage



Gain = 1

Figure 23. Gain Error vs Reference Voltage

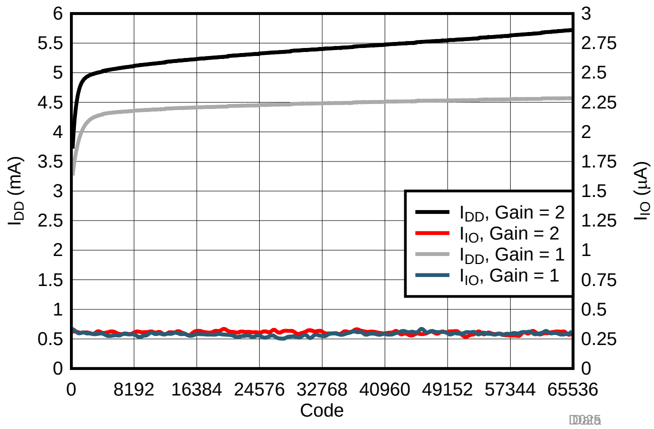


Gain = 1

Figure 24. Full Scale Error vs Reference Voltage

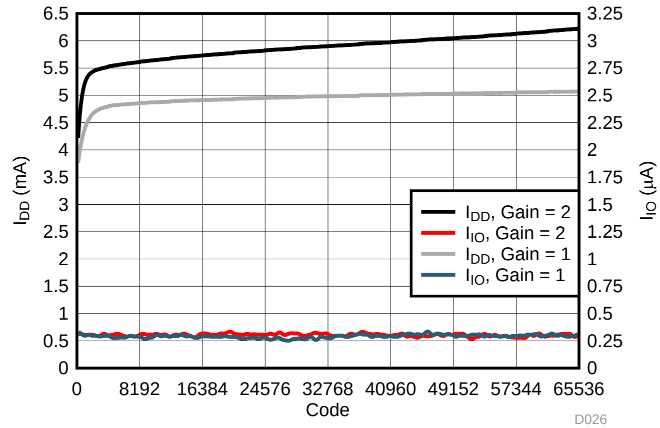
Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.



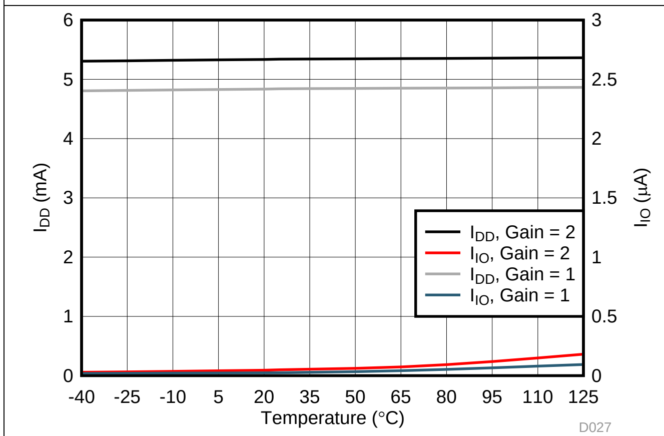
Gain = 1. External Reference = 2.5 V

Figure 25. Supply Current with External Reference vs Digital Input Code



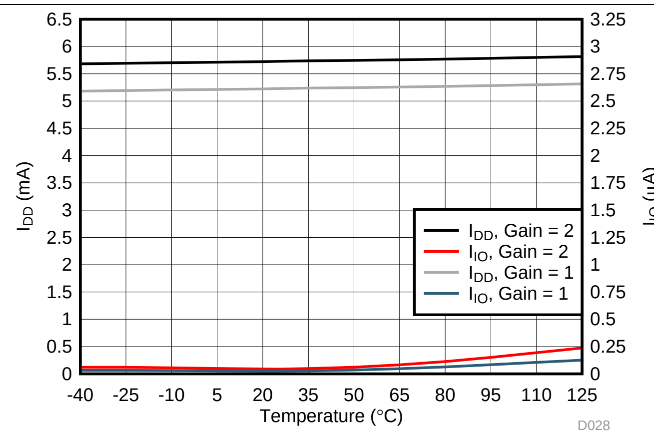
Gain = 1

Figure 26. Supply Current with Internal Reference vs Digital Input Code



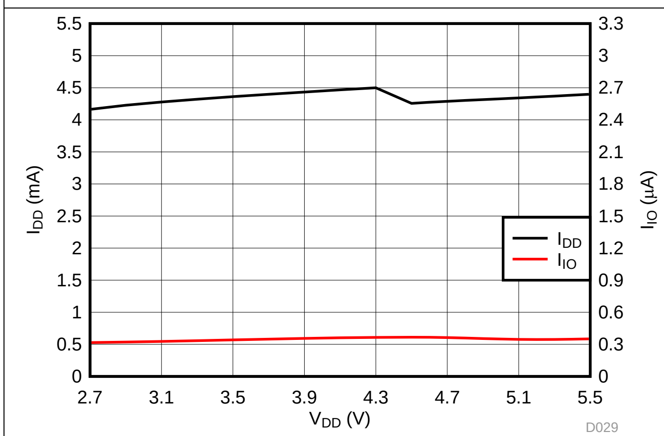
Gain = 1. External Reference = 2.5 V

Figure 27. Supply Current with External Reference vs Temperature



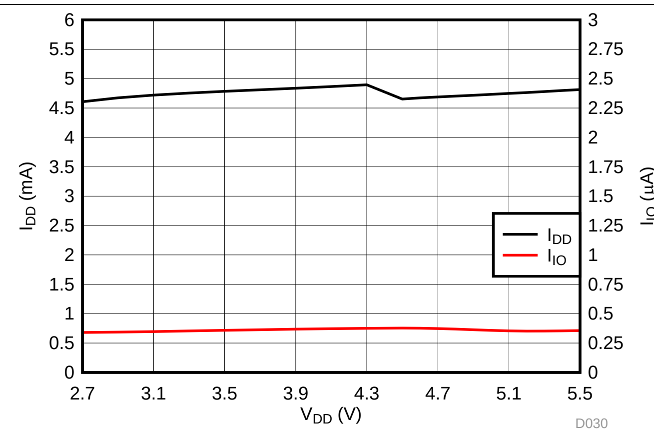
Gain = 1

Figure 28. Supply Current with Internal Reference vs Temperature



Gain = 1. External Reference = 2.5 V

Figure 29. Supply Current with External Reference vs Supply Voltage



Gain = 1

Figure 30. Supply Current with Internal Reference vs Supply Voltage

Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.

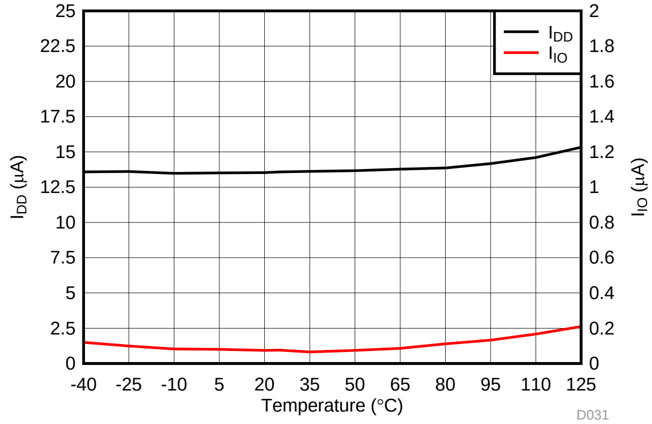


Figure 31. Power Down Current vs Temperature

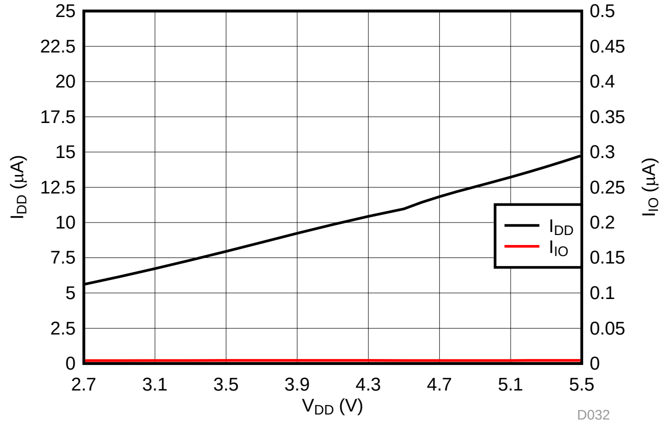


Figure 32. Power Down Current vs Supply Voltage

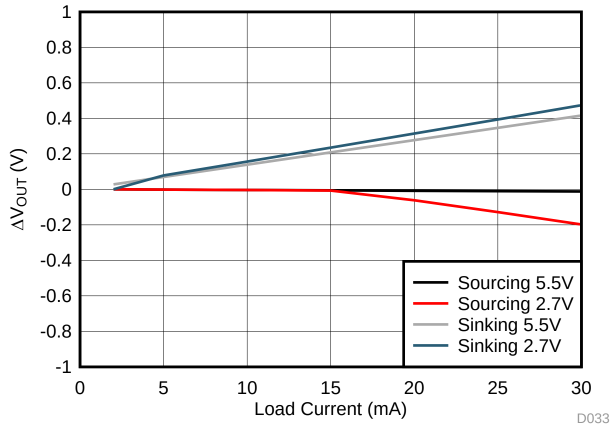


Figure 33. Headroom/Footroom vs Load Current

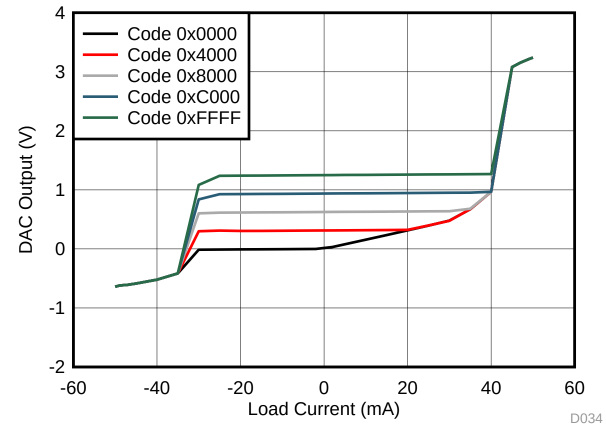


Figure 34. Source and Sink Capability with Gain = ½

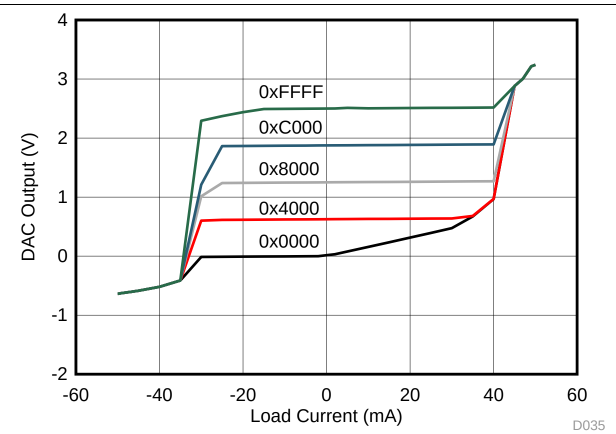


Figure 35. Source and Sink Capability with Gain = 1

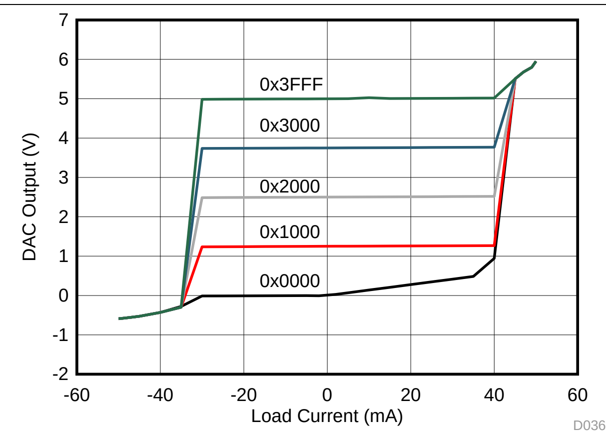
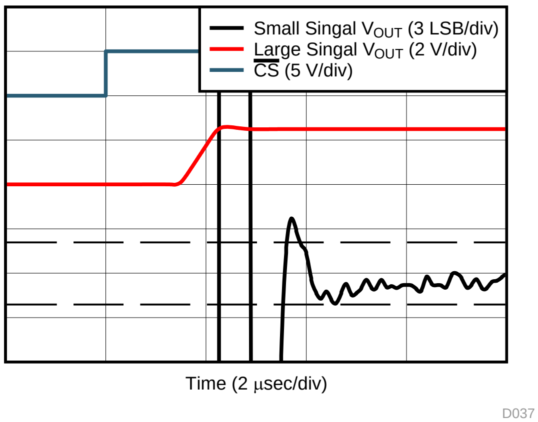


Figure 36. Source and Sink Capability with Gain = 2

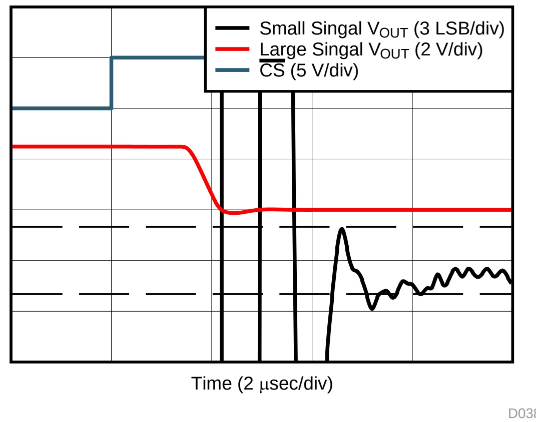
Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.



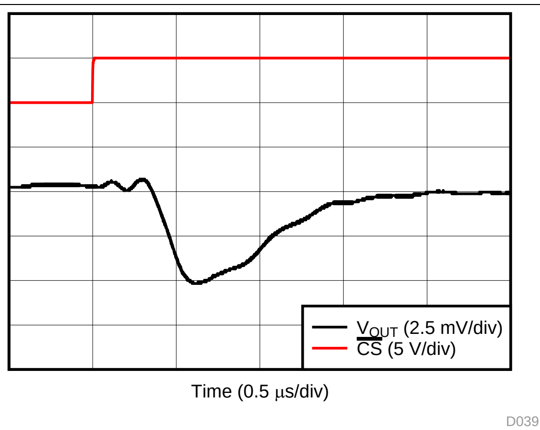
Gain = 1

Figure 37. Full-Scale Settling Time, Rising Edge



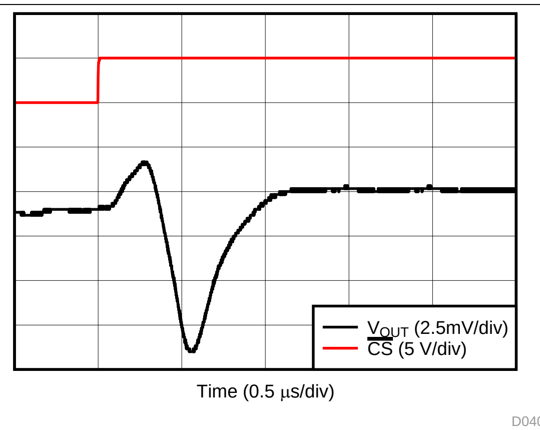
Gain = 1

Figure 38. Full-Scale Settling Time, Falling Edge



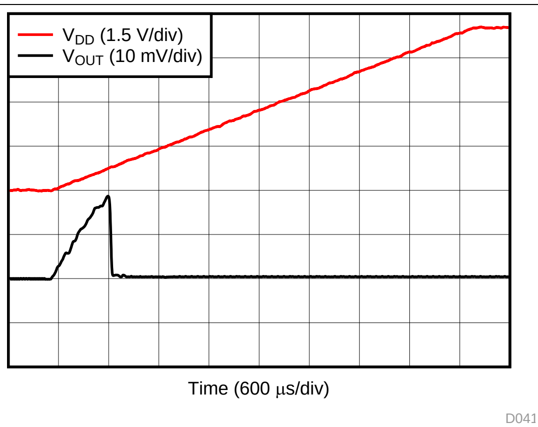
Gain = 1

Figure 39. Glitch Impulse, Falling Edge, 1 LSB Step



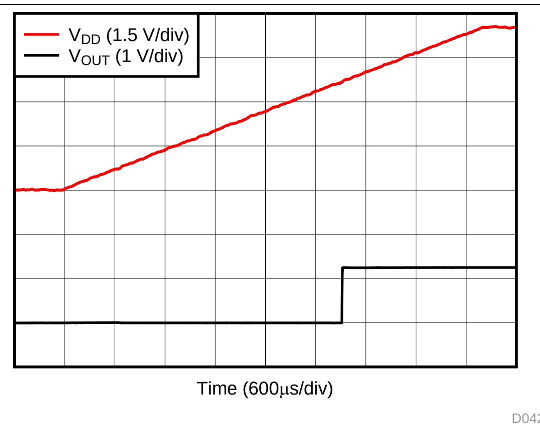
Gain = 1

Figure 40. Glitch Impulse, Rising Edge, 1 LSB Step



Gain = 1

Figure 41. Power-On, Reset to Zero Scale

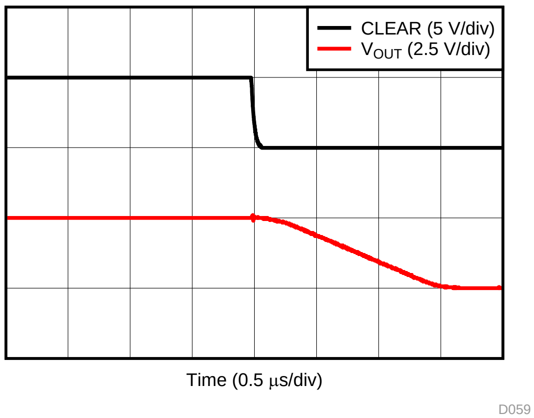


Gain = 1

Figure 42. Power-On, Reset to Midscale

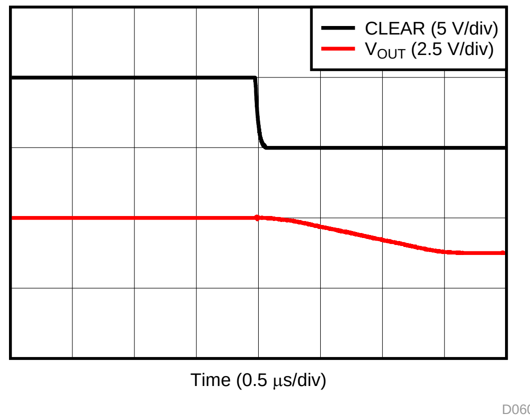
Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.



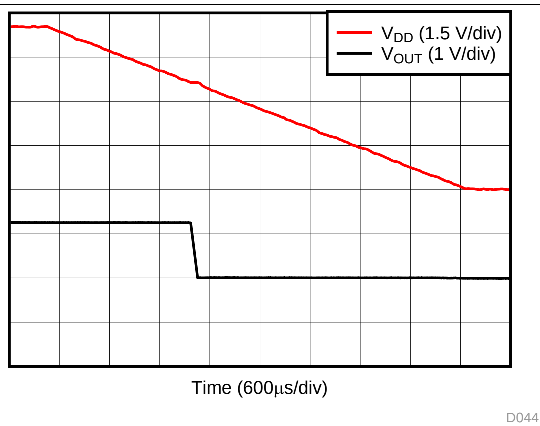
Gain = 1

Figure 43. DACx0508C, Clear to Zero Scale



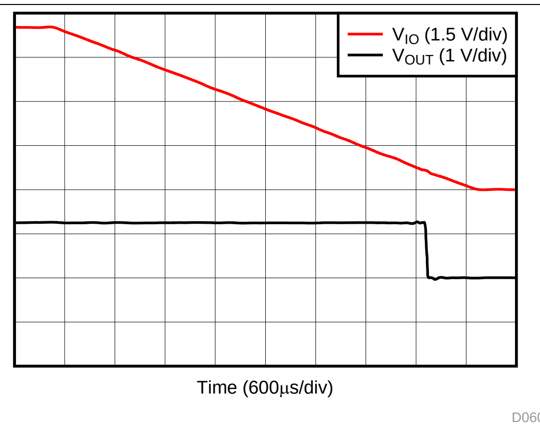
Gain = 1

Figure 44. DACx0508C, Clear to Midscale



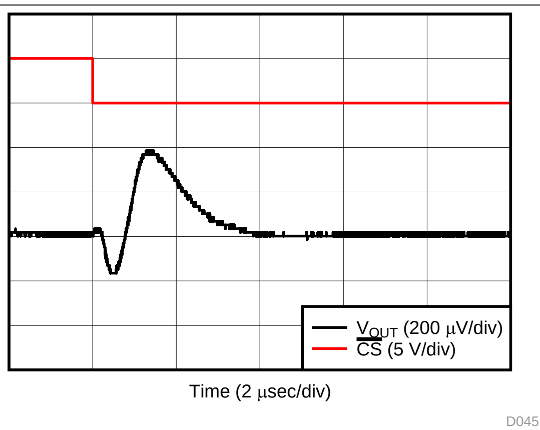
Gain = 1. DAC code at midscale

Figure 45. V_{DD} Power-Down



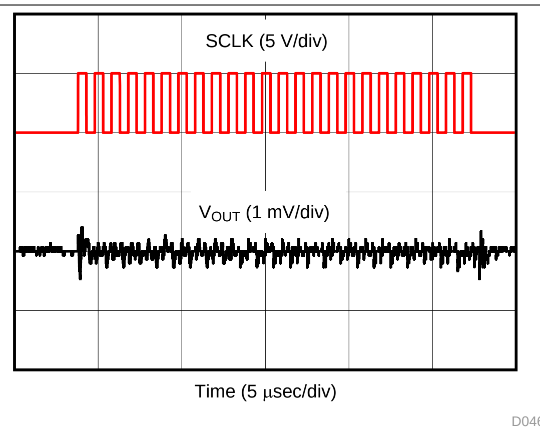
Gain = 1. DAC code at midscale

Figure 46. V_{IO} Power-Down



Gain = 1. Measured DAC at midscale. All other DACs switch from code 32 to full scale

Figure 47. Channel to Channel Crosstalk

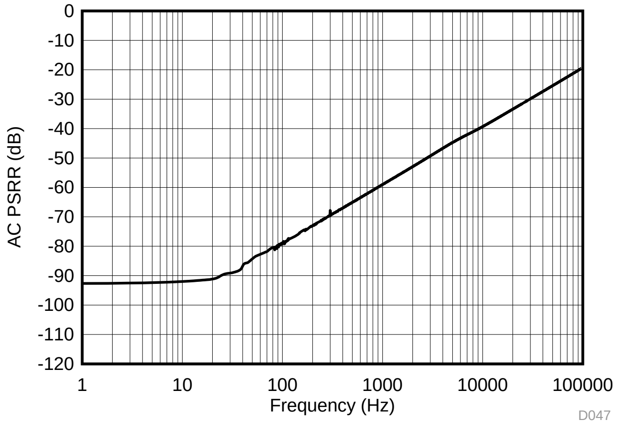


Gain = 1. DAC code at midscale

Figure 48. Clock Feedthrough with SCLK = 1 MHz

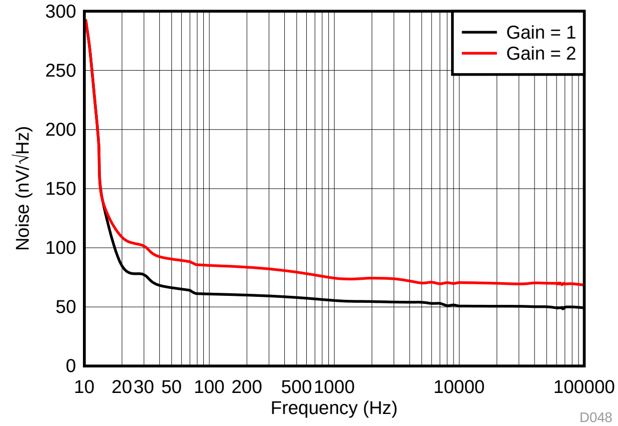
Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.



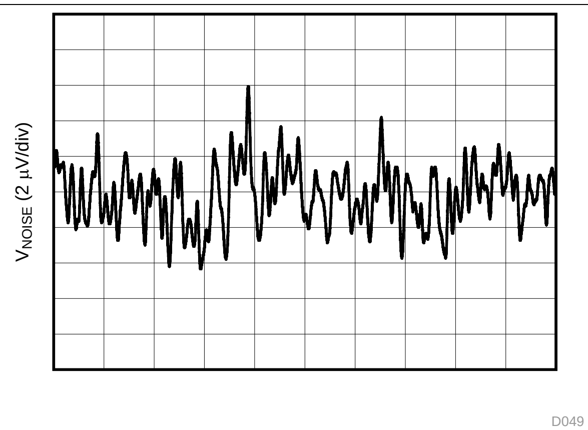
Gain = 1. V_{DD} = 5 V + 200 mV_{PP} (Sinusoid). DAC code at fullscale

Figure 49. DAC Output AC PSRR vs Frequency



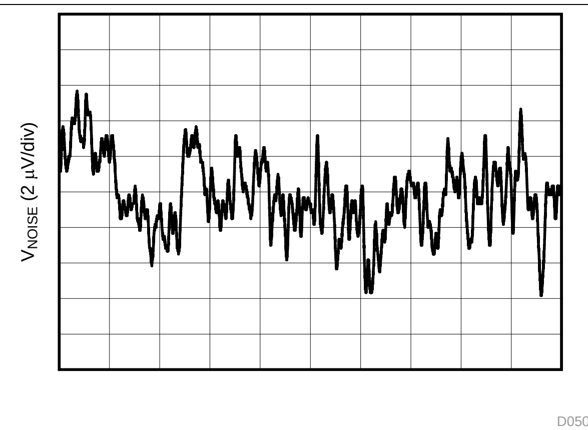
External Reference = 2.5 V. DAC code at midscale

Figure 50. DAC Output Noise Density vs Frequency



Gain = 1. External Reference = 2.5 V. DAC code at midscale

Figure 51. DAC Output Noise with External Reference 0.1 Hz to 10 Hz



Gain = 1. DAC code at midscale

Figure 52. DAC Output Noise with Internal Reference 0.1 Hz to 10 Hz

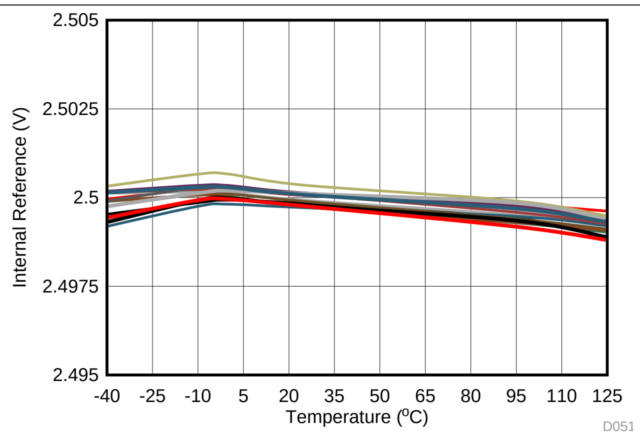


Figure 53. Internal Reference Voltage vs Temperature

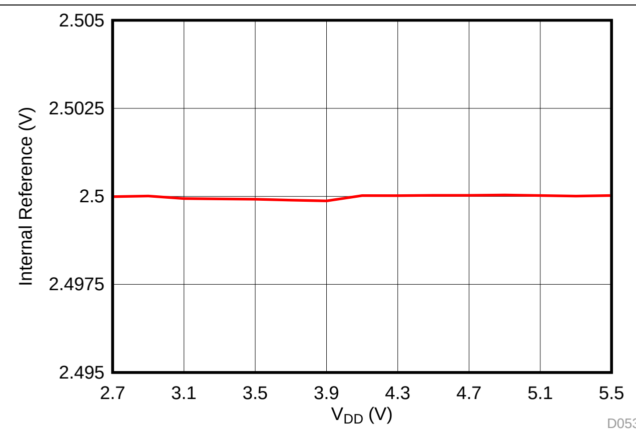


Figure 54. Internal Reference Voltage vs Supply Voltage

Typical Characteristics (continued)

At T_A = 25°C, V_{DD} = 5.5 V, Internal Reference = 2.5 V, Gain = 2, DAC outputs unloaded, unless otherwise noted.

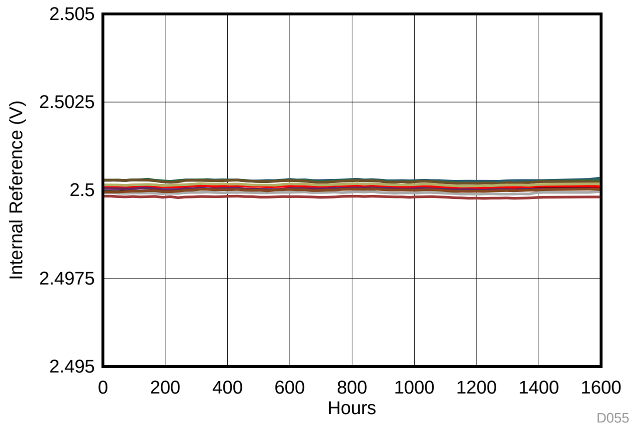


Figure 55. Internal Reference Voltage vs Time

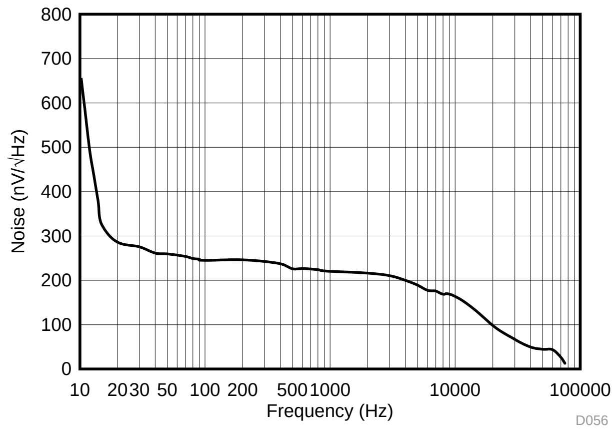
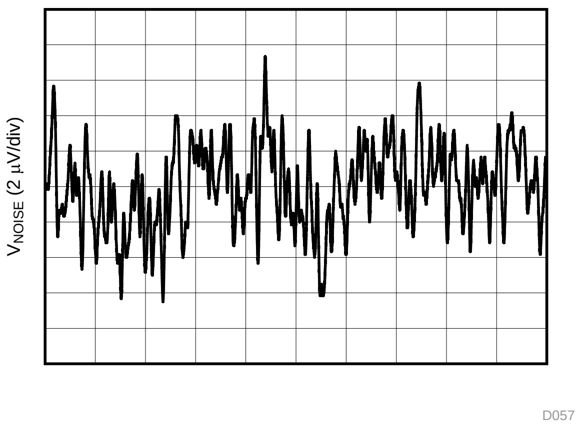


Figure 56. Internal Reference Noise Density vs Frequency



0.1 Hz to 10 Hz

Figure 57. Internal Reference Noise

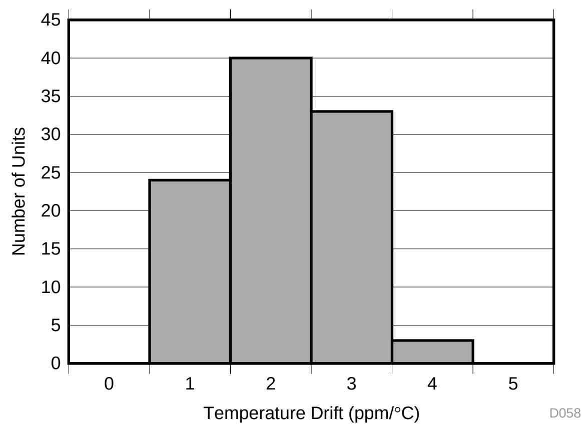


Figure 58. Internal Reference Temperature Drift Histogram

9 Detailed Description

9.1 Overview

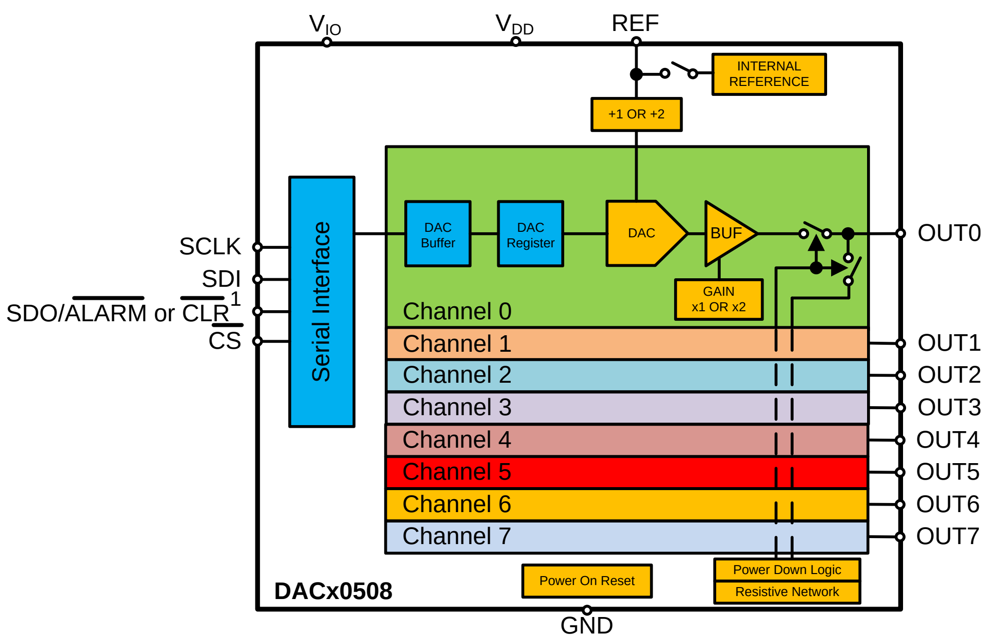
The DACx0508 is a pin-compatible family of low-power, eight-channel, buffered voltage-output digital-to-analog converters (DACs) with 16-, 14- and 12-bit resolution. The DACx0508 includes a 2.5 V internal reference and user selectable gain configuration providing full scale output voltages of 1.25 V (gain = ½), 2.5 V (gain = 1) or 5 V (gain = 2). The device operates from a single 2.7 V to 5.5 V supply, is specified monotonic, and provides high linearity of ±1 LSB INL.

Communication to the DACx0508 is performed through a serial interface that supports stand-alone and daisy-chain operation. The optional frame-error checking provides added robustness to the DACx0508 serial interface.

The DACx0508 incorporates a power-on-reset circuit that powers up and maintains the DAC outputs at either zero scale or midscale until a valid code is written to the device.

A dedicated clear pin (DACx0508C) enables a simultaneous update of multiple DAC channels to their power-on-reset value.

9.2 Functional Block Diagram



[1]SDO/ALARM (DACx0508), CLR (DACx0508C)

9.3 Feature Description

9.3.1 Digital-to-Analog Converter (DAC) Architecture

Each output channel in the DACx0508 consists of an R-2R ladder architecture followed by an output buffer amplifier. Figure 59 shows a block diagram of the DAC architecture.

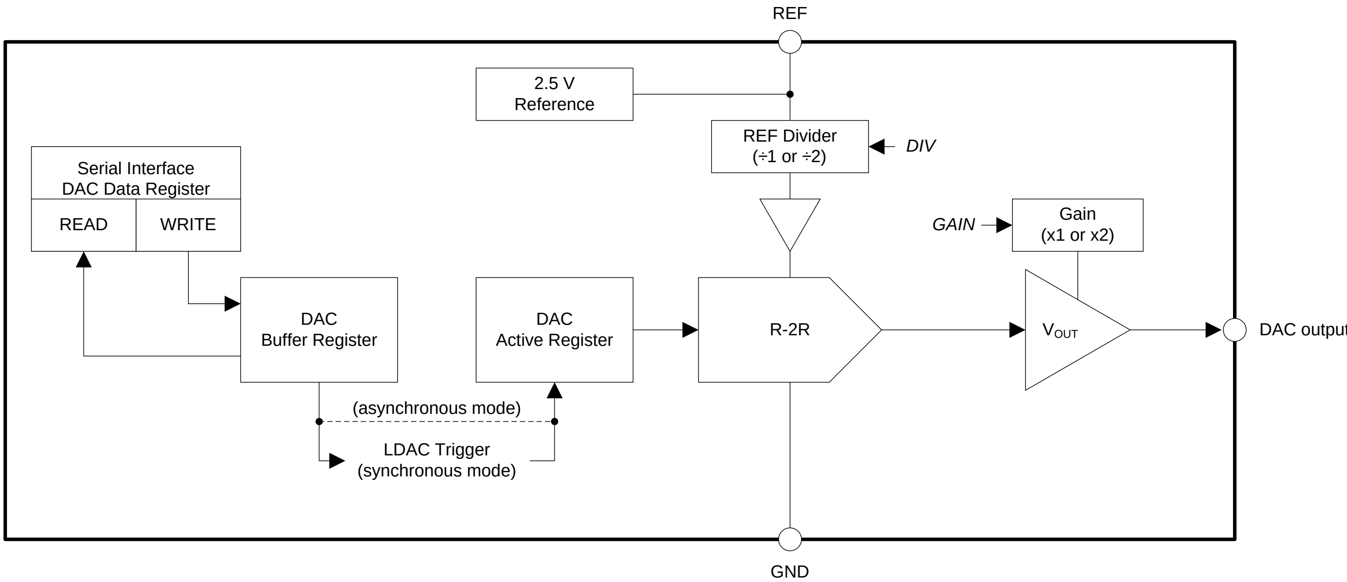


Figure 59. DACx0508 DAC Block Diagram

9.3.1.1 DAC Transfer Function

The input data are written to the individual DAC Data registers in straight binary format. After a power-on or a reset event, all DAC registers are set to either zero code (DACx0508Z) or midscale code (DACx0508M). The DAC transfer function is given by Equation 1.

$$V_{OUT} = \frac{CODE}{2^n} \times \frac{V_{REF}}{DIV} \times GAIN \quad (1)$$

where:

- CODE = decimal equivalent of the binary code that is loaded to the DAC register. CODE ranges from 0 to $2^n – 1$.
- V_{REF} = DAC reference voltage. Either V_{REFOUT} from the internal 2.5 V reference or V_{REFIN} if using an external one.
- n = resolution in bits. Either 12 (DAC60508), 14 (DAC70508) or 16 (DAC80508).
- DIV = 1 or 2 as set by the REF-DIV bit in the GAIN register. Set to 1 by default.
- GAIN = 1 or 2 as set by the BUFF-GAIN bit for that DAC channel in the GAIN register. Set to 1 by default in DACx0508Z and to 2 in DACx0508M.

Feature Description (continued)

9.3.1.2 Output Amplifiers

The DACx0508 output buffer amplifier is capable of generating rail-to-rail voltages on its output, giving a maximum output range of 0 V to V_{DD}. Each buffer amplifier is capable of driving a load of 2 kΩ in parallel with 10 nF to GND.

The full-scale output voltage for each channel is determined by the reference voltage (V_{REF}), the reference divider setting (DIV), and the output buffer gain for that channel (GAIN), as shown in Table 1. During normal operation the DIV and GAIN settings can be reconfigured through the REF-DIV and BUFF-GAIN bit (See Equation 1). The GAIN setting for each output channel can be individually configured thus enabling independent output voltage ranges for each DAC output.

Table 1. DAC Output Range Configuration

DIV Setting	GAIN Setting	DAC OUTPUT RANGE
÷2	×1	0 V to ½ × V_{REF}
÷1	×1	Not recommended
÷2	×2	0 V to V_{REF}
÷1	×2	0 V to 2 × V_{REF}

9.3.1.3 DAC Register Structure

Data written to the DAC data registers is initially stored in the DAC buffer registers. Transfer of data from the DAC buffer registers to the active DAC registers can be configured to happen immediately (asynchronous mode) or initiated by an LDAC trigger (synchronous mode). Once the DAC active registers are updated, the DAC outputs change to their new values. When the host reads from a DAC Data register, the value held in the DAC buffer register is returned (not the value held in the DAC active register).

9.3.1.3.1 DAC Register Synchronous and Asynchronous Updates

The update mode for each DAC channel is determined by the status of its corresponding SYNC-EN bit. In asynchronous mode, a write to the DAC data register results in an immediate update of the DAC active register and DAC output on $\overline{CS}$ rising edge. In synchronous mode, writing to the DAC data register does not automatically update the DAC output. Instead the update occurs only after an LDAC trigger event. An LDAC trigger is generated through the LDAC bit in the TRIGGER register. The synchronous update mode enables simultaneous update of multiple DAC outputs. In both update modes a minimum wait time of 1 µs is required between DAC output updates.

9.3.1.3.2 Broadcast DAC Register

The DAC broadcast register enables a simultaneous update of multiple DAC outputs with the same value with a single register write. Each DAC channel can be configured to update or remain unaffected by a broadcast command by setting the corresponding DAC-BRDCAST-EN bit in the SYNC register. A register write to the BRDCAST-DATA register forces those DAC channels that have been configured for broadcast operation to update their outputs. The DAC ouputs update to the broadcast value on $\overline{CS}$ rising edge independently of their synchronous mode configuration.

9.3.1.3.3 CLEAR Operation (DACx0508C only)

The $\overline{CLR}$ pin enables a simultaneous update of multiple DAC channels to the clear value: zero code (DACx0508ZC) or midscale code (DACx0508MC). DAC channels 0 through 3 and channels 4 through 7 can be independently configured to update or remain unaffected by the $\overline{CLR}$ pin by setting the corresponding CLR-MSK bit. A $\overline{CLR}$ pin logic low forces those DAC channels that have been configured for clear operation to clear the contents of their buffer and active registers to the clear value and sets the analog outputs accordingly, regardless of their synchronization setting. Those channels not configured for clear operation retain their buffer and active register contents as well as the corresponding analog outputs even if a clear command is issued. While the $\overline{CLR}$ pin is kept low, register writes to the DAC data registers of those channels set for clear operation are ignored. A logic high on the $\overline{CLR}$ pin causes the device to exit clear mode.

9.3.2 Internal Reference

The DACx0508 includes a 2.5 V precision bandgap reference enabled by default. Operation from an external reference is supported by disabling the internal reference in the CONFIG register. The internal reference is externally available at the REF pin.

A minimum 150 nF capacitor is recommended between the reference output and GND for noise filtering.

9.3.2.1 Reference Divider

The reference voltage to the device, either from the internal reference or an external one can be divided by a factor of two by setting the REF-DIV bit in the GAIN register to 1 during normal operation. The reference voltage divider provides additional flexibility in setting the full-scale output voltage for each DAC output and must be configured so that there is sufficient headroom from V_{DD} to the DAC operating reference voltage (V_{REF}/DIV). See the Recommended Operating Conditions table for more information.

Improper configuration of the reference divider issues a reference alarm condition. In this case, the reference buffer is shut down, and all the DAC outputs go to 0 V. The DAC data registers are unaffected by the alarm condition thus enabling the DAC output to return to normal operation once the reference divider is configured correctly. The reference alarm status can be read from the REF-ALM bit in the STATUS register. Additionally by setting ALM-EN = 1 and ALM-SEL = 1 in the CONFIG register, the SDO/$\overline{\text{ALARM}}$ pin is configured as a reference alarm pin.

9.3.2.2 Solder Heat Reflow

A known behavior of IC reference voltage circuits is the shift induced by the soldering process. Figure 60 and Figure 61 show the effect of solder heat reflow for the DACx0508 internal reference.

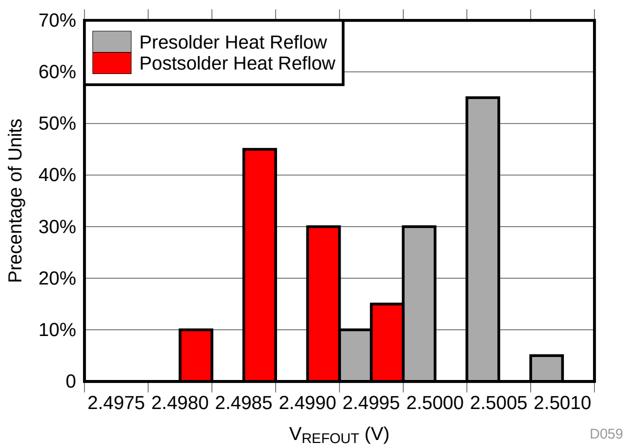


Figure 60. DAC70508 and DAC60508 Solder Heat Reflow Reference Voltage Shift

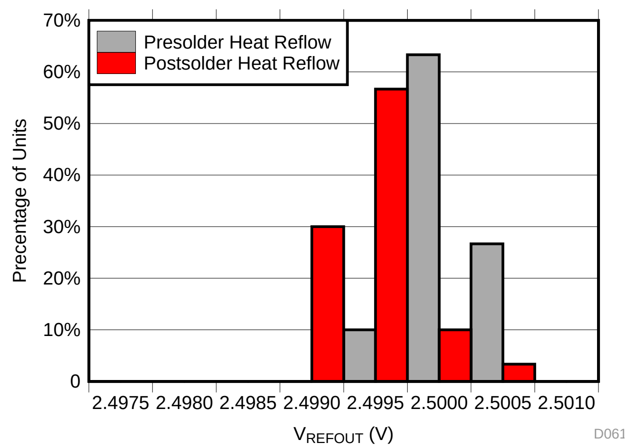


Figure 61. DAC80508 Solder Heat Reflow Reference Voltage Shift

9.3.3 Device Reset Options

9.3.3.1 Power-on-Reset (POR)

The DACx0508 includes a power-on reset function that controls the output voltage at power up. After the V_{DD} and V_{IO} supplies have been established a POR event is issued. The POR causes all registers to initialize to their default values and communication with the device is valid only after a 250 µs power-on-reset delay. The default value for all DACs in the DACx0508Z devices is zero-code and midscale-code for the DACx0508M ones. Each DAC channel remains at the power-up voltage until a valid command is written to it.

The POR circuit requires specific supply levels to discharge the internal capacitors and to reset the device on power up, as indicated in Figure 62 and Figure 63. In order to ensure a POR event, V_{DD} or V_{IO} must be below their corresponding low thresholds for at least 100 µs. If V_{DD} and V_{IO} remain above their specified high threshold a POR event will not occur. When the supplies drop below their high threshold but remain over the lower one (shown as the undefined region), the device may or may not reset under all specified temperature and power-supply conditions.

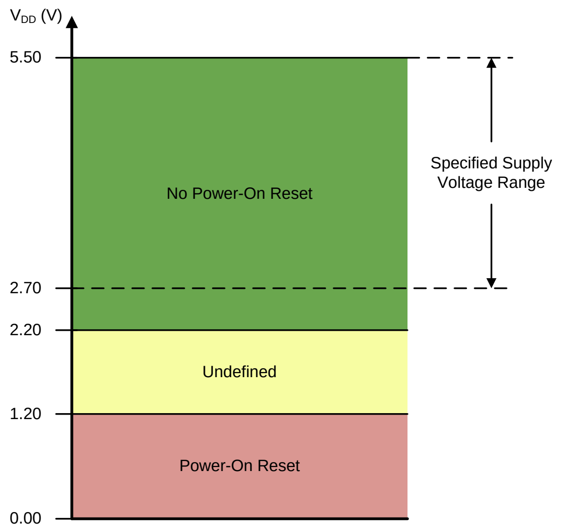


Figure 62. Threshold Levels for V_{DD} POR Circuit

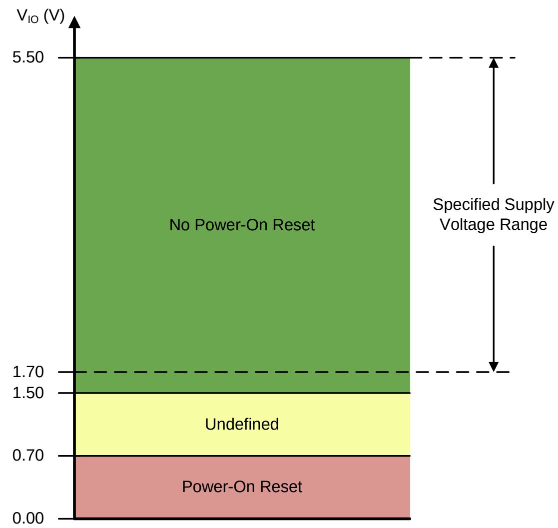


Figure 63. Threshold Levels for V_{IO} POR Circuit

9.3.3.2 Software Reset

A device software reset event is initiated by writing the reserved code 0x1010 to SOFT-RESET in the TRIGGER register. The software reset command is triggered on the $\overline{CS}$ rising edge of the instruction. A software reset initiates a POR event.

9.4 Device Functional Modes

9.4.1 Stand-Alone Operation

A serial interface access cycle is initiated by asserting the $\overline{CS}$ pin low. The serial clock SCLK can be a continuous or gated clock. SDI data are clocked on SCLK falling edges. A regular serial interface access cycle is 24 bits long with error checking disabled and 32 bits long with error checking enabled, thus the $\overline{CS}$ pin must stay low for at least 24 or 32 SCLK falling edges. The access cycle ends when the $\overline{CS}$ pin is de-asserted high. If the access cycle contains less than the minimum clock edges, the communication is ignored. If the access cycle contains more than the minimum clock edges, only the last 24 or 32 bits are used by the device. When $\overline{CS}$ is high, the SCLK and SDI signals are blocked and the SDO pin is in a Hi-Z state.

In an error checking disabled access cycle (24-bits long) the first byte input to SDI is the instruction cycle which identifies the request as a read or write command and the 4-bit address to be accessed. The following bits in the cycle form the data cycle, as shown in Table 2.

Table 2. Serial Interface Access Cycle

BIT	FIELD	DESCRIPTION
23	RW	Identifies the communication as a read or write command to the addressed register. R/W = 0 sets a write operation. R/W = 1 sets a read operation.
22:20	Reserved	Reserved bits. Must be filled with zeros.
19:16	A[3:0]	Register address. Specifies the register to be accessed during the read or write operation.
15:0	DI[15:0]	Data cycle bits. If a write command, the data cycle bits are the values to be written to the register with address A[3:0]. If a read command, the data cycle bits are don't care values.

A read operation is initiated by issuing a read command access cycle. After the read command, a second access cycle must be issued to get the requested data, as shown in Table 3. Data are clocked out on SDO pin either on the falling edge or rising edge of SCLK according to the FSDO bit in the CONFIG register.

Table 3. SDO Output Access Cycle

BIT	FIELD	DESCRIPTION
23	RW	Echo RW from previous access cycle.
22:20	Reserved	Echo bits 22:20 from previous access cycle (all zeros).
19:16	A[3:0]	Echo address from previous access cycle.
15:0	DO[15:0]	Readback data requested on previous access cycle.

9.4.2 Daisy-Chain Operation

For systems that contain more than one DACx0508 devices, the SDO pin can be used to daisy-chain them together. Daisy-chain operation is useful in reducing the number of serial interface lines.

The first falling edge on the $\overline{CS}$ pin starts the operation cycle. If more than 24 SCLK pulses are applied while the $\overline{CS}$ pin is kept low, the data ripples out of the shift register and is clocked out on the SDO pin either on the falling edge or rising edge of SCLK according to the FSDO bit. By connecting the SDO output of the first device to the SDI input of the next device in the chain, a multiple-device interface is constructed. Each device in the system requires 24 clock pulses. As a result the total number of clock cycles must be equal to 24 × N, where N is the total number of DACx0508 devices in the daisy chain. When the serial transfer to all devices is complete the $\overline{CS}$ signal is taken high. This action transfers the data from the serial peripheral interface (SPI) shift registers to the internal registers of each device in the daisy chain and prevents any further data from being clocked into the input shift register.

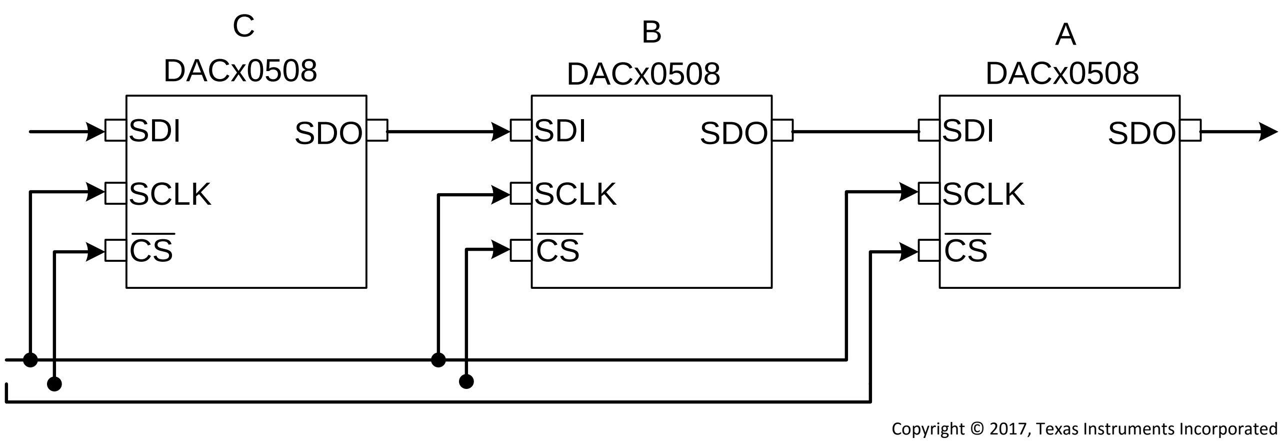


Figure 64. Daisy-Chain Layout

9.4.3 Frame Error Checking

If the DACx0508 is used in a noisy environment, error checking can be used to check the integrity of SPI data communication between the device and the host processor. This feature can be enabled by setting the CRC-EN bit in the CONFIG register.

The error checking scheme is based on the CRC-8-ATM (HEC) polynomial $x^8 + x^2 + x + 1$ (that is, 100000111). When error checking is enabled, the serial interface access cycle width is 32 bits. The normal 24-bit SPI data is appended with an 8-bit CRC polynomial by the host processor before feeding it to the device, as shown in Table 4. In all serial interface readback operations the CRC polynomial is output on the SDO pin as part of the 32-bit cycle.

Table 4. Error Checking Serial Interface Access Cycle

BIT	FIELD	DESCRIPTION
31	RW	Identifies the communication as a read or write command to the addressed register. R/W = 0 sets a write operation. R/W = 1 sets a read operation.
30	CRC-ERROR	Reserved bit. Set to zero.
29:28	Reserved	Reserved bits. Must be filled with zeros.
27:24	A[3:0]	Register address. Specifies the register to be accessed during the read or write operation.
23:8	DI[15:0]	Data cycle bits. If a write command, the data cycle bits are the values to be written to the register with address A[3:0]. If a read command, the data cycle bits are don't care values.
7:0	CRC	8-bit CRC polynomial.

The DACx0508 decodes the 32-bit access cycle to compute the CRC remainder on $\overline{CS}$ rising edges. If no error exists, the CRC remainder is zero and data are accepted by the device.

A write operation failing the CRC check causes the data to be ignored by the device. After the write command, a second access cycle can be issued to determine the error checking result (CRC-ERROR bit) on the SDO pin, as shown in Table 5. Additionally, by setting ALM-EN = 1 and ALM-SEL = 0 in the CONFIG register, the SDO/$\overline{ALARM}$ pin is configured as a CRC alarm pin.

Table 5. Write Operation Error Checking Cycle

BIT	FIELD	DESCRIPTION
31	RW	Echo RW from previous access cycle (RW = 0).
30	CRC-ERROR	Returns a 1 when a CRC error is detected, 0 otherwise.
29:28	Reserved	Echo bits 29:28 from previous access cycle (all zeros).
27:24	A[3:0]	Echo address from previous access cycle.
23:8	DO[15:0]	Echo data from previous access cycle.
7:0	CRC	Calculated CRC value of bits 31:8.

A read operation must be followed by a second access cycle to get the requested data on the SDO pin. The error check result (CRC-ERROR bit) from the read command is output on the SDO pin, as shown in Table 6. As in the case of a write operation failing the CRC check, the SDO/$\overline{\text{ALARM}}$ pin if configured as a CRC alarm pin can be used to indicate a read command CRC failure.

Table 6. Read Operation Error Checking Cycle

BIT	FIELD	DESCRIPTION
31	RW	Echo RW from previous access cycle (RW = 1).
30	CRC-ERROR	Returns a 1 when a CRC error is detected, 0 otherwise.
29:28	Reserved	Echo bits 29:28 from previous access cycle (all zeros).
27:24	A[3:0]	Echo address from previous access cycle.
23:8	DO[15:0]	Readback data requested on previous access cycle.
7:0	CRC	Calculated CRC value of bits 31:8.

9.4.4 Power-Down Mode

The DACx0508 DAC output amplifiers and internal reference can be independently powered down through the CONFIG register. At power-up all output channels and the device internal referece are active by defaul. A DAC output channel in power-down mode is connected internally to GND through a 1 kΩ resistor.

9.5 Programming

The DACx0508 is controlled through a flexible serial interface that is compatible with SPI type interfaces used on many microcontrollers and DSP controllers. Table 7 shows the SPI timing requirements. Figure 65 and Figure 66 show the SPI write and read timing diagrams, respectively.

Table 7. Programming Timing Requirements(1)

		V_{IO} = 1.7 V to 2.7 V			V_{IO} = 2.7 V to 5.5 V			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
SERIAL INTERFACE – WRITE OPERATION								
f_{SCLK}	SCLK frequency			50			50	MHz
$t_{SCLKHIGH}$	SCLK high time	9			9			ns
$t_{SCLKLOW}$	SCLK low time	9			9			ns
t_{SDIS}	SDI setup	5			5			ns
t_{SDIH}	SDI hold	10			10			ns
t_{CSS}	$\overline{CS}$ to SCLK falling edge setup	13			13			ns
t_{CSH}	SCLK falling edge to $\overline{CS}$ rising edge	10			10			ns
t_{CSHIGH}	$\overline{CS}$ high time	15			15			ns
$t_{CSIGNORE}$	SCLK falling edge to $\overline{CS}$ ignore	7			7			ns
SERIAL INTERFACE – READ AND DAISY CHAIN OPERATION, FSDO = 0								
f_{SCLK}	SCLK frequency			12			18	MHz
$t_{SCLKHIGH}$	SCLK high time	35			25			ns
$t_{SCLKLOW}$	SCLK low time	35			25			ns
t_{SDIS}	SDI setup	5			5			ns
t_{SDIH}	SDI hold	10			10			ns
t_{CSS}	$\overline{CS}$ to SCLK falling edge setup	32			20			ns
t_{CSH}	SCLK falling edge to $\overline{CS}$ rising edge	10			10			ns
t_{CSHIGH}	$\overline{CS}$ high time	15			15			ns
t_{SDODLY}	SDO output delay from SCLK rising edge	3.5		33.5	3.5		23	ns
t_{SDODZ}	SDO driven to tri-state	0		30	0		25	ns
$t_{CSIGNORE}$	SCLK falling edge to $\overline{CS}$ ignore	7			7			ns
SERIAL INTERFACE – READ AND DAISY CHAIN OPERATION, FSDO = 1								
f_{SCLK}	SCLK frequency			20			25	MHz
$t_{SCLKHIGH}$	SCLK high time	22			18			ns
$t_{SCLKLOW}$	SCLK low time	22			18			ns
t_{SDIS}	SDI setup	5			5			ns
t_{SDIH}	SDI hold	10			10			ns
t_{CSS}	$\overline{CS}$ to SCLK falling edge setup	32			20			ns
t_{CSH}	SCLK falling edge to $\overline{CS}$ rising edge	10			10			ns
t_{CSHIGH}	$\overline{CS}$ high time	15			15			ns
t_{SDODLY}	SDO output delay from SCLK falling edge	3.5		45	3.5		32	ns
t_{SDODZ}	SDO driven to tri-state	0		30	0		25	ns
$t_{CSIGNORE}$	SCLK falling edge to $\overline{CS}$ ignore	7			7			ns
DIGITAL LOGIC								
$t_{RSTDLYPOR}$	POR reset delay		170	250		170	250	µs
$t_{DACWAIT}$	Sequential DAC output updates	1			1			µs
t_{CLR}	$\overline{CLR}$ pulse	20			20			ns
t_{CLRD}	$\overline{CLR}$ delay(2)			100			100	ns

(1) All input signals are specified with t_R = t_F = 1 ns/V (10% to 90% of V_{IO}), timed from a voltage level of (V_{IL} + V_{IH})/2, V_{DD} = 2.7 V to 5.5 V, V_{IO} = 1.7 V to 5.5 V, V_{REFIN} = 1.25 V to 5.5 V, SDO loaded with 20 pF, T_A = -40°C to +125°C
(2) Specified from a logic-low on $\overline{CLR}$ pin to when the DAC output starts to change. In the special case when the DAC output is at GND or V_{DD}, the $\overline{CLR}$ delay may be as long as 1 µs

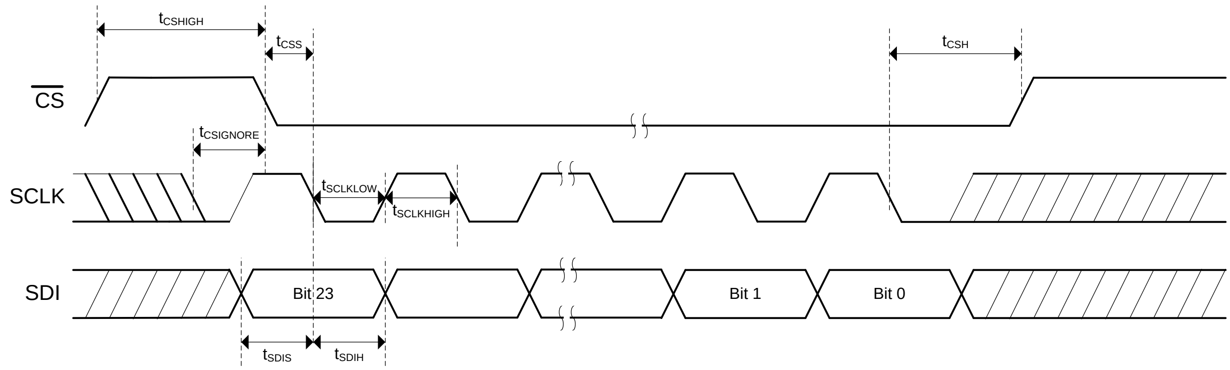


Figure 65. Serial Interface Write Timing Diagram

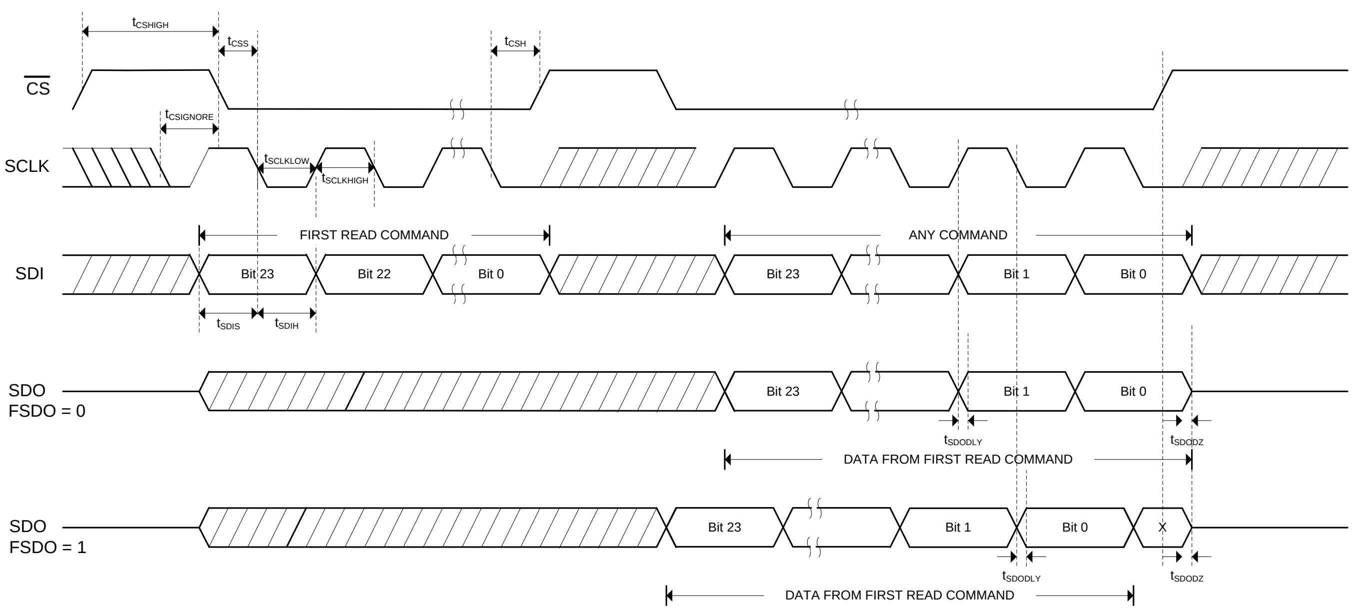


Figure 66. Serial Interface Read Timing Diagram

9.6 Register Map

Table 8. Register Map

<table>
<tr><th rowspan="2">REGISTER</th><th rowspan="2">TYPE</th><th rowspan="2">RESET</th><th colspan="4">ADDRESS BITS</th><th colspan="16">DATA BITS</th></tr>
<tr><th>A3</th><th>A2</th><th>A1</th><th>A0</th><th>D15</th><th>D14</th><th>D13</th><th>D12</th><th>D11</th><th>D10</th><th>D9</th><th>D8</th><th>D7</th><th>D6</th><th>D5</th><th>D4</th><th>D3</th><th>D2</th><th>D1</th><th>D0</th></tr>
<tr><td>NOP</td><td>W</td><td>0000</td><td>0</td><td>0</td><td>0</td><td>0</td><td colspan="16">NOP</td></tr>
<tr><td>DEVICE ID</td><td>R</td><td>—</td><td>0</td><td>0</td><td>0</td><td>1</td><td colspan="14">DEVICEID</td><td colspan="2">VERSIONID</td></tr>
<tr><td>SYNC</td><td>R/W</td><td>FF00</td><td>0</td><td>0</td><td>1</td><td>0</td><td colspan="8">DACx-BRDCAST-EN</td><td colspan="8">DACx-SYNC-EN</td></tr>
<tr><td>CONFIG</td><td>R/W</td><td>0000</td><td>0</td><td>0</td><td>1</td><td>1</td><td colspan="2">RESERVED</td><td>ALM SEL</td><td>ALM EN</td><td>CRC EN</td><td>F SDO</td><td>D SDO</td><td>REF PW DWN</td><td colspan="8">DACx-PWDWN</td></tr>
<tr><td>GAIN</td><td>R/W</td><td>0000</td><td>0</td><td>1</td><td>0</td><td>0</td><td colspan="5">RESERVED</td><td>CLR-4TO7-MSK (1)</td><td>CLR-0TO3-MSK (1)</td><td>REF DIV-EN</td><td colspan="8">BUFFx-GAIN</td></tr>
<tr><td>TRIGGER</td><td>W</td><td>0000</td><td>0</td><td>1</td><td>0</td><td>1</td><td colspan="11">RESERVED</td><td>L DAC</td><td colspan="4">SOFT-RESET[3:0]</td></tr>
<tr><td>BRDCAST</td><td>R/W</td><td>0000</td><td>0</td><td>1</td><td>1</td><td>0</td><td colspan="16">BRDCAST-DATA[15:0]</td></tr>
<tr><td>STATUS</td><td>R/W</td><td>0000</td><td>0</td><td>1</td><td>1</td><td>1</td><td colspan="15">RESERVED</td><td>REF ALM</td></tr>
<tr><td>DAC0</td><td>R/W</td><td>0000</td><td>1</td><td>0</td><td>0</td><td>0</td><td colspan="16">DAC0-DATA[15:0]</td></tr>
<tr><td>DAC1</td><td>R/W</td><td>0000</td><td>1</td><td>0</td><td>0</td><td>1</td><td colspan="16">DAC1-DATA[15:0]</td></tr>
<tr><td>DAC2</td><td>R/W</td><td>0000</td><td>1</td><td>0</td><td>1</td><td>0</td><td colspan="16">DAC2-DATA[15:0]</td></tr>
<tr><td>DAC3</td><td>R/W</td><td>0000</td><td>1</td><td>0</td><td>1</td><td>1</td><td colspan="16">DAC3-DATA[15:0]</td></tr>
<tr><td>DAC4</td><td>R/W</td><td>0000</td><td>1</td><td>1</td><td>0</td><td>0</td><td colspan="16">DAC4-DATA[15:0]</td></tr>
<tr><td>DAC5</td><td>R/W</td><td>0000</td><td>1</td><td>1</td><td>0</td><td>1</td><td colspan="16">DAC5-DATA[15:0]</td></tr>
<tr><td>DAC6</td><td>R/W</td><td>0000</td><td>1</td><td>1</td><td>1</td><td>0</td><td colspan="16">DAC6-DATA[15:0]</td></tr>
<tr><td>DAC7</td><td>R/W</td><td>0000</td><td>1</td><td>1</td><td>1</td><td>1</td><td colspan="16">DAC7-DATA[15:0]</td></tr>
<tr><td>All Others</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td>—</td><td colspan="16">RESERVED</td></tr>
</table>

(1) DACx0508C only. Reserved bits in DACx0508.

9.6.1 NOP Register (address = 0x00) [reset = 0x0000]

Figure 67. NOP Register

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
NOP															
W															

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 9. NOP Register Field Descriptions

Bit	Field	Type	Reset	Description
15:0	NOP	W	0x0000	No operation. Write 0000h for proper no-operation command

9.6.2 DEVICE ID Register (address = 0x01) [reset = 0x---]

Figure 68. DEVICE ID Register

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
DEVICEID														VERSIONID	
R														R	

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 10. DEVICE ID Field Descriptions

Bit	Field	Type	Reset	Description
15:2	DEVICEID	R	----	Device ID: D15 Reserved - 0 D14:12 Resolution - 000 (16-bit); 001 (14-bit); 010 (12-bit) D11:8 Channels - 1000 (8 channels) D7 Reset - 0 (DACx0508Z: reset to zero); 1 (DACx0508M: reset-to-midscale) D6:2 Reserved - 00101
1:0	VERSIONID	R	10	Version ID. Subject to change

9.6.3 SYNC Register (address = 0x2) [reset = 0xFF00]

Figure 69. SYNC Register

15	14	13	12	11	10	9	8
DAC7-BRDCAST-EN	DAC6-BRDCAST-EN	DAC5-BRDCAST-EN	DAC4-BRDCAST-EN	DAC3-BRDCAST-EN	DAC2-BRDCAST-EN	DAC1-BRDCAST-EN	DAC0-BRDCAST-EN
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
7	**6**	**5**	**4**	**3**	**2**	**1**	**0**
DAC7-SYNC-EN	DAC6-SYNC-EN	DAC5-SYNC-EN	DAC4-SYNC-EN	DAC3-SYNC-EN	DAC2-SYNC-EN	DAC1-SYNC-EN	DAC0-SYNC-EN
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 11. SYNC Register Field Descriptions

Bit	Field	Type	Reset	Description
15	DAC7-BRDCAST-EN	R/W	1	When set to 1 the corresponding DAC is set to update its output after a serial interface write to the BRDCAST register. When cleared to 0 the corresponding DAC output remains unaffected after a serial interface write to the BRDCAST register.
14	DAC6-BRDCAST-EN	R/W	1	
13	DAC5-BRDCAST-EN	R/W	1	
12	DAC4-BRDCAST-EN	R/W	1	
11	DAC3-BRDCAST-EN	R/W	1	
10	DAC2-BRDCAST-EN	R/W	1	
9	DAC1-BRDCAST-EN	R/W	1	
8	DAC0-BRDCAST-EN	R/W	1	
7	DAC7-SYNC-EN	R/W	0	When set to 1 the corresponding DAC output is set to update in response to an LDAC trigger (synchronous mode). When cleared to 0 the corresponding DAC output is set to update immediately on a $\overline{CS}$ rising edge (asynchronous mode).
6	DAC6-SYNC-EN	R/W	0	
5	DAC5-SYNC-EN	R/W	0	
4	DAC4-SYNC-EN	R/W	0	
3	DAC3-SYNC-EN	R/W	0	
2	DAC2-SYNC-EN	R/W	0	
1	DAC1-SYNC-EN	R/W	0	
0	DAC0-SYNC-EN	R/W	0	

9.6.4 CONFIG Register (address = 0x3) [reset = 0x0000]

Figure 70. CONFIG Register

15	14	13	12	11	10	9	8
Reserved		ALM-SEL	ALM-EN	CRC-EN	FSDO	DSDO	REF-PWDWN
—		R/W	R/W	R/W	R/W	R/W	R/W
7	**6**	**5**	**4**	**3**	**2**	**1**	**0**
DAC7-PWDWN	DAC6-PWDWN	DAC5-PWDWN	DAC4-PWDWN	DAC3-PWDWN	DAC2-PWDWN	DAC1-PWDWN	DAC0-PWDWN
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 12. CONFIG Register Field Descriptions

Bit	Field	Type	Reset	Description
15:14	Reserved	—	00	Reserved for factory use
13	ALM-SEL	R/W	0	ALARM select. 0: ALARM pin is CRC-ERROR 1: ALARM pin is REF-ALARM
12	ALM-EN	R/W	0	Configure SDO/ALARM pin. When 1: SDO/ALARM pin is an active-low, open-drain, alarm pin. An external 10 kΩ pullup resistor to V_{IO} is required. FSDO and DSDO bits are ignored. When 0: SDO/ALARM pin is a serial interface, push-pull, SDO pin
11	CRC-EN	R/W	0	CRC enable bit. Set to 1 to enable CRC. Set to 0 to disable
10	FSDO	R/W	0	Fast SDO bit (half-cycle speedup). When 0, SDO updates on an SCLK rising edge. When 1, SDO updates a half-cycle earlier, during an SCLK falling edge.
9	DSDO	R/W	0	Disable SDO bit. When 1, SDO is always tri-stated. When 0, SDO is driven while CS is low, and tri-stated while CS is high
8	REF-PWDWN	R/W	0	When set to 1 disables the device internal reference
7	DAC7-PWDWN	R/W	0	When set to 1 the corresponding DAC is set in power-down mode and its output is connected to GND through a 1 kΩ internal resistor.
6	DAC6-PWDWN	R/W	0	
5	DAC5-PWDWN	R/W	0	
4	DAC4-PWDWN	R/W	0	
3	DAC3-PWDWN	R/W	0	
2	DAC2-PWDWN	R/W	0	
1	DAC1-PWDWN	R/W	0	
0	DAC0-PWDWN	R/W	0	

9.6.5 GAIN Register (address = 0x04) [reset = 0x---]

Figure 71. GAIN Register

15	14	13	12	11	10	9	8
Reserved					Reserved/ CLR-4TO7-MSK [(1)]	Reserved/ CLR-0TO3-MSK [(1)]	REFDIV-EN
—					R/W	R/W	R/W
7	**6**	**5**	**4**	**3**	**2**	**1**	**0**
BUFF7-GAIN	BUFF6-GAIN	BUFF5-GAIN	BUFF4-GAIN	BUFF3-GAIN	BUFF2-GAIN	BUFF1-GAIN	BUFF0-GAIN
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

(1) DACx0508C only. Reserved bits in DACx0508.

Table 13. GAIN Register Field Descriptions

Bit	Field	Type	Reset	Description
15:11	Reserved	—	0	Reserved for factory use.
10	Reserved / CLR-4TO7-MSK	R/W	0	DACx0508. Reserved for factory use. DACx0508C. When cleared to 0 the corresponding DAC group is set to clear in response to a logic-low value on the CLR pin. When set to 1 the corresponding DAC group remains unaffected by the CLR pin.
9	Reserved / CLR-0TO3-MSK	R/W	0	
8	REFDIV-EN	R/W	0/1	When set to 1 the reference voltage is internally divided by a factor of 2. When cleared to 0 the reference voltage is unaffected.
7	BUFF7-GAIN	R/W	0/1	When set to 1 the buffer amplifier for corresponding DAC has a gain of 2. Default value for the DACx0508M devices. When cleared to 0 the buffer amplifier for corresponding DAC has a gain of 1. Default value for the DACx0508Z devices.
6	BUFF6-GAIN	R/W	0/1	
5	BUFF5-GAIN	R/W	0/1	
4	BUFF4-GAIN	R/W	0/1	
3	BUFF3-GAIN	R/W	0/1	
2	BUFF2-GAIN	R/W	0/1	
1	BUFF1-GAIN	R/W	0/1	
0	BUFF0-GAIN	R/W	0/1	

9.6.6 TRIGGER Register (address = 0x05) [reset = 0x0000]

Figure 72. TRIGGER Register

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved											LDAC	SOFT-RESET[3:0]			
—											W	W			

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 14. TRIGGER Register Field Descriptions

Bit	Field	Type	Reset	Description
15:5	Reserved	—	0	Reserved for factory use.
4	LDAC	W	0	Set this bit to 1 to synchronously load those DACs that have been set in synchronous mode in the SYNC register.
3:0	SOFT-RESET[3:0]	W	0x0	When set to the reserved code 1010 resets the device to its default state.

9.6.7 BRDCAST Register (address = 0x6) [reset = 0x0000]

Figure 73. BRDCAST Register

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
BRDCAST-DATA[15:0]															
R/W															

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 15. BRDCAST Register Field Descriptions

Bit	Field	Type	Reset	Description
15:0	BRDCAST-DATA[15:0]	R/W	0x0000	Writing to the BRDCAST register forces those DAC channels that have been set to broadcast in the SYNC register to update their active data register with the BRDCAST-DATA value. Data are MSB aligned in straight binary format and follows the format below: DAC80508: { DATA[15:0] } DAC70508: { DATA[13:0], x, x } DAC60508: { DATA[11:0], x, x, x, x } x – Don't care bits

9.6.8 STATUS Register (address = 0x7) [reset = 0x0000]

Figure 74. STATUS Register

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Reserved															REF-ALM
—															R/W

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 16. STATUS Register Field Descriptions

Bit	Field	Type	Reset	Description
15:1	Reserved	—	0	Reserved for factory use.
0	REF-ALM	R	0	Reference alarm bit. Reads 1 when the difference between V_{REF}/DIV and V_{DD} is below the required minimum analog threshold. Reads 0 otherwise.

9.6.9 DACx Register (address = 0x8 to 0xF) [reset = 0x0000 or 0x8000]

Figure 75. DACx Register

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
DACx-DATA[15:0]															
R/W															

LEGEND: R/W = Read/Write; R = Read only; -n = value after reset

Table 17. DACx Register Field Descriptions

Bit	Field	Type	Reset	Description
15:0	DACx-DATA[15:0]	R/W	0x0000 or 0x8000	Stores the 16-, 14- or 12-bit data to be loaded to DACx in MSB aligned straight binary format. The default value is zero-code for the DACx0508Z devices and midscale-code for the DACx0508M ones. Data follows the format below: DAC80508: { DATA[15:0] } DAC70508: { DATA[13:0], x, x } DAC60508: { DATA[11:0], x, x, x, x } x – Don't care bits

10 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

The high linearity, small package size and wide temperature range make the DACx0508 suitable in applications such as optical networking, wireless infrastructure, industrial automation and data acquisition systems. The device incorporates a 2.5 V internal reference with an internal reference divider circuit that enables full-scale DAC output voltages of 1.25 V, 2.5 V, or 5 V.

10.1.1 Interfacing to Microcontroller

Figure 76 displays a typical serial interface that may be observed when connecting the DACx0508 SPI serial interface to a (master) microcontroller type platform. The setup for the interface is as follows: The microcontroller output SPI CLK drives the SCLK pin of the DACx0508, while the DACx0508 SDI pin is driven by the MOSI pin of the microcontroller. The $\overline{CS}$ pin of the DACx0508 can be asserted from a general program input/output pin of the microcontroller. When data are to be transmitted to the DACx0508, the $\overline{CS}$ pin is taken low. The data from the microcontroller is then transmitted to the DACx0508, totaling 24 bits latched into the DACx0508 device through the falling edge of SCLK. $\overline{CS}$ is then brought high after the completed write. The DACx0508 requires data with the MSB as the first bit received.

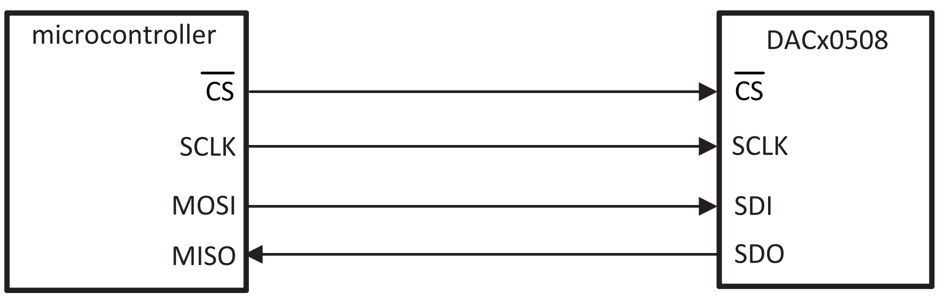


Figure 76. Typical Serial Interface

Application Information (continued)

10.1.2 Programmable Current Source Circuit

The DACx0508 can be integrated into the circuit in Figure 77 to implement an improved Howland current pump for precise voltage to current conversions. Bidirectional current flow and high voltage compliance are two features of the circuit. With a matched resistor network, the load current of the circuit is shown by Equation 2.

$$I_L = \frac{(R2 + R3) / R1}{R3} \times V_{REF} \times \frac{CODE}{2^n} \tag{2}$$

The value of R3 in Equation 2 can be reduced to increase the output current drive of U3. U3 can drive ±20 mV in both directions with voltage compliance limited up to 15 V by the U3 voltage supply. Elimination of the circuit compensation capacitor C1 in the circuit is not suggested as a result of the change in the output impedance Z_O, according to Equation 3.

$$Z_O = \frac{\left(R1^{'}\right)\left(R3\right)\left(R1 + R2\right)}{R1\left(R2^{'} + R3^{'}\right) - R1^{'}\left(R2 + R3\right)} \tag{3}$$

As shown in Equation 3, with matched resistors, Z_O is infinite and the circuit is optimum for use as a current source. However, if unmatched resistors are used, Z_O is positive or negative with negative output impedance being a potential cause of oscillation. Therefore, by incorporating C1 into the circuit, possible oscillation problems are eliminated. The value of C1 can be determined for critical applications; for most applications, however, a value of several pF is suggested.

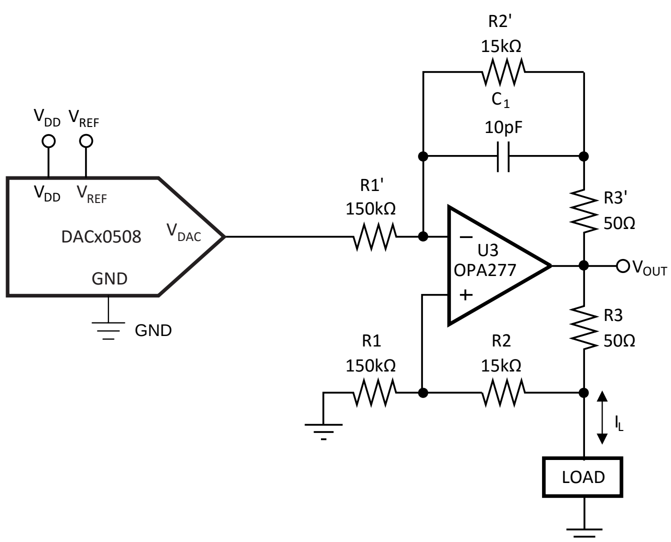


Figure 77. Programmable Bidirectional Current Source Circuit

10.2 Typical Application

The DACx0508 is designed for single-supply operation; however, a bipolar output is also possible using the circuit shown in Figure 78.

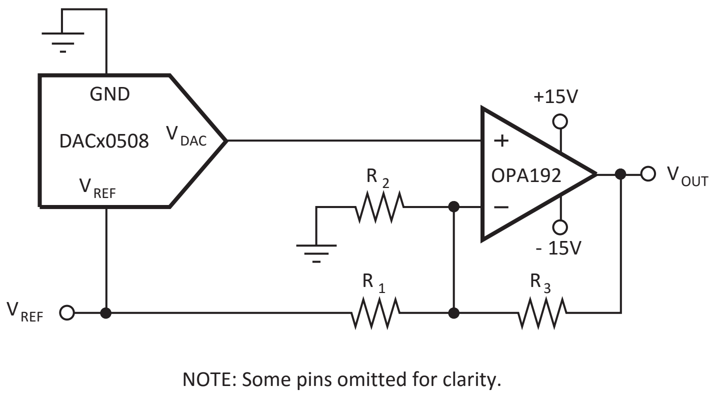


Figure 78. Bipolar Operation Using the DACx0508

10.2.1 Design Requirements

The circuit shown in Figure 78 gives a bipolar output voltage at V_{OUT}. When GAIN = 1, V_{OUT} can be calculated using Equation 4:

$$V_{OUT}(CODE) = \left[\left(V_{REF} \times \frac{CODE}{2^n}\right)\left(1 + \frac{R_3}{R_2} + \frac{R_3}{R_1}\right) - \left(V_{REF} \times \frac{R_3}{R_1}\right)\right] \quad (4)$$

Where:
- $V_{OUT}(CODE)$ = output voltage versus code
- CODE = 0 to 2^n – 1. This is the digital code loaded to the DAC
- V_{REF} = reference voltage applied to the DACx0508
- n = resolution in bits. Either 12 (DAC60508), 14 (DAC70508) or 16 (DAC80508)

Table 18. Design Parameters

PARAMETER	VALUE
V_{OUT}	±10 V
V_{REF}	2.5 V
n	12

10.2.2 Detailed Design Procedure

The bipolar output span can be calculated through Equation 4 by defining a few parameters, the first being the value for the reference voltage. Once a reference voltage is chosen, the gain resistors can be set accordingly by determining the desired V_{OUT} at code 0 and code 2^n. For a V_{REF} of 2.5 V and a desired output voltage range of ±10 V the calculation is as follows.

CODE = 0:

$$V_{OUT}(0) = -\left(V_{REF} \times \frac{R_3}{R_1}\right) = -\left(2.5V \times \frac{R_3}{R_1}\right) \quad (5)$$

Setting the equation to minimum output span, $V_{OUT}(0)$ = –10 V, will reduce the equation to: $R_3/R_1 = 4$:

CODE = 4096:

Setting the equation to maximum output scan, $V_{OUT}(4096)$ = 10 V, and R_3/R_1 = 4 will reduce the equation to: $R_3/R_2 = 3$

It is important to note that the maximum code of a 12-bit DAC is 4095; code 4096 was used to simplify the equation above. For practical use, the true output span will encompass a range of –10 V to (10 V – 1 LSB), which in this case is –10 V to 9.995 V.

10.2.3 Application Curve

The ±10 V output span with a reference voltage of 2.5 V can be achieved by using values of 30 kΩ, 10 kΩ, and 7.5 kΩ for R3, R2, and R1 respectively. A curve to illustrate this output span is shown in Figure 79. Note: 1% tolerance resistors were used in evaluating bipolar operation.

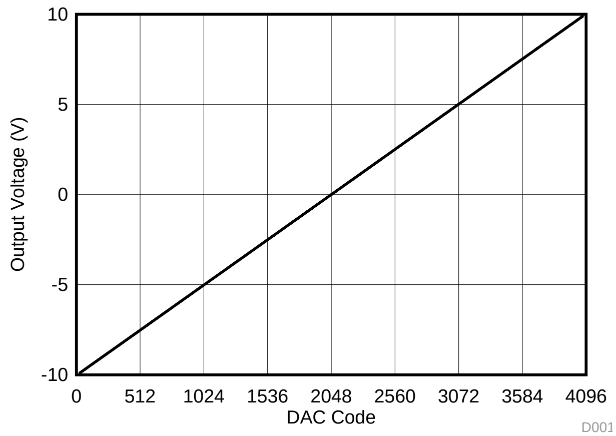


Figure 79. Bipolar Operation

11 Power Supply Recommendations

The DACx0508 operates within the specified V_{DD} supply range of 2.7 V to 5.5 V and V_{IO} supply range of 1.7 V to 5.5 V. The DACx0508 does not require specific supply sequencing.

The V_{DD} supply must be well-regulated and low-noise. Switching power supplies and dc/dc converters often have high frequency glitches or spikes riding on the output voltage. In addition, digital components can create similar high frequency spikes. This noise can easily couple into the DAC output voltage through various paths between the power connections and analog output. In order to further minimize noise from the power supply, include a 1-μF to 10-μF capacitor and 0.1-μF bypass capacitor. The current consumption on the V_{DD} pin, the short-circuit current limit, and the load current for the device is listed in the *Electrical Characteristics*. The power supply must meet the aforementioned current requirements.

12 Layout

12.1 Layout Guidelines

A precision analog component requires careful layout, the list below provides some insight into good layout practices.

- Bypass all power supply pins to ground with a low ESR ceramic bypass capacitor. The typical recommended bypass capacitance is 0.1- to 0.22-µF ceramic with a X7R or NP0 dielectric.
- Place power supplies and REF bypass capacitors close to the pins to minimize inductance and optimize performance.
- Use a high-quality ceramic type NP0 or X7R for its optimal performance across temperature, and very low dissipation factor.
- The digital and analog sections must have proper placement with respect to the digital pins and analog pins of the DACx0508 device. The separation of analog and digital blocks minimizes coupling into neighboring blocks, as well as interaction between analog and digital return currents.

12.2 Layout Examples

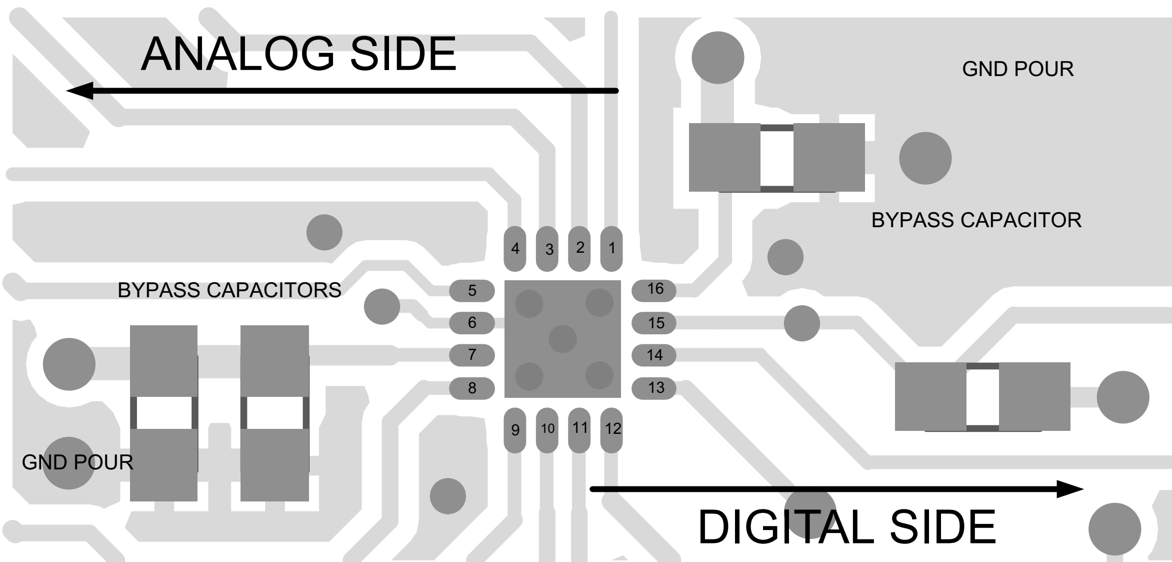


Figure 80. DACx0508 QFN Layout Example

Layout Examples (continued)

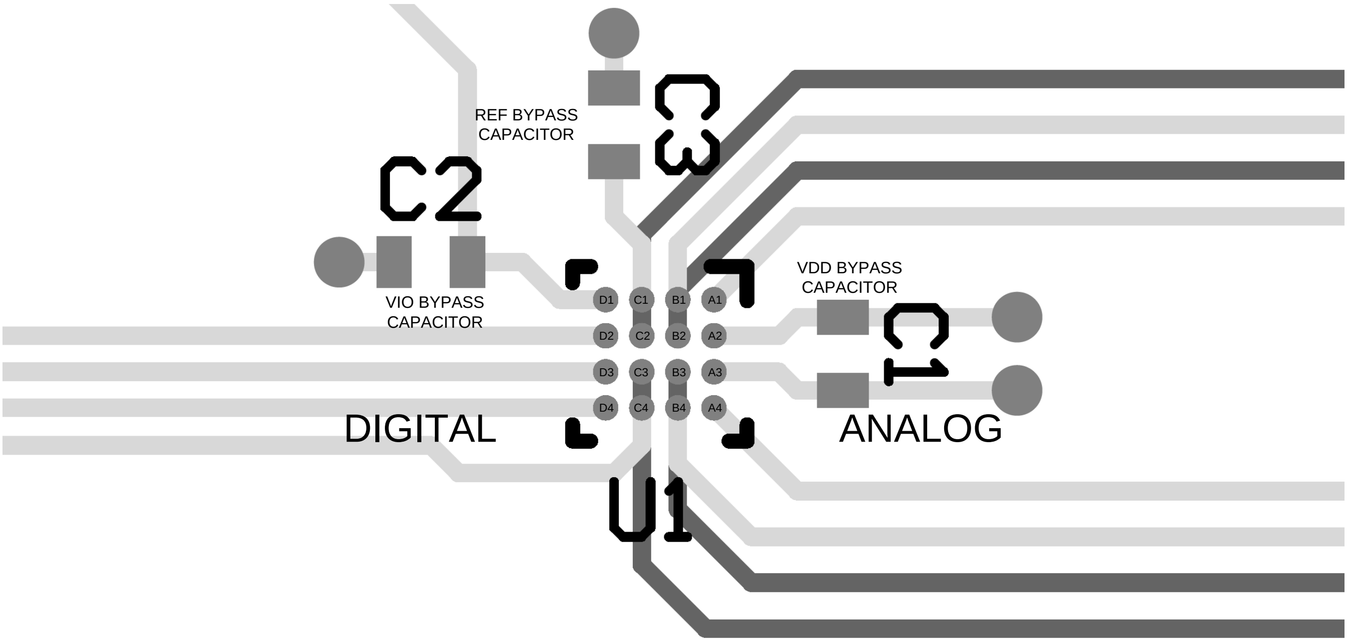


Figure 81. DACx0508 DSBGA Layout Example

13 デバイスおよびドキュメントのサポート

13.1 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびサンプル注文またはご購入へのクイック・アクセスが含まれます。

表 19. 関連リンク

製品	プロダクト・フォルダ	ご注文はこちら	技術資料	ツールとソフトウェア	サポートとコミュニティ
DAC80508	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
DAC70508	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
DAC60508	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

13.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.comのデバイス製品フォルダを開いてください。右上の隅にある「*通知を受け取る*」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

13.3 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

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設計サポート ***TIの設計サポート*** 役に立つE2Eフォーラムや、設計サポート・ツールをすばやく見つけることができます。技術サポート用の連絡先情報も参照できます。

13.4 商標

E2E is a trademark of Texas Instruments.
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13.5 静電気放電に関する注意事項

これらのデバイスは、限定的なESD（静電破壊）保護機能を内 蔵しています。保存時または取り扱い時は、MOSゲートに対す る静電破壊を防止するために、リード線同士をショートさせて おくか、デバイスを導電フォームに入れる必要があります。

13.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DAC60508MCRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658MC
DAC60508MCRTER.A	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658MC
DAC60508MCRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658MC
DAC60508MCRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658MC
DAC60508MCRTET.A	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658MC
DAC60508MCRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658MC
DAC60508MCYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65MC
DAC60508MCYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65MC
DAC60508MCYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65MC
DAC60508MCYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65MC
DAC60508MRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658M
DAC60508MRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658M
DAC60508MRTERG4	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658M
DAC60508MRTERG4.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658M
DAC60508MRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658M
DAC60508MRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658M
DAC60508MYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65M
DAC60508MYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65M
DAC60508MYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65M
DAC60508MYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65M
DAC60508ZCRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658ZC
DAC60508ZCRTER.A	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658ZC
DAC60508ZCRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658ZC
DAC60508ZCRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658ZC
DAC60508ZCRTET.A	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658ZC
DAC60508ZCRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658ZC
DAC60508ZCYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65ZC
DAC60508ZCYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65ZC
DAC60508ZCYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65ZC

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DAC60508ZCYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65ZC
DAC60508ZRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658Z
DAC60508ZRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658Z
DAC60508ZRTERG4	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658Z
DAC60508ZRTERG4.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658Z
DAC60508ZRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658Z
DAC60508ZRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	658Z
DAC60508ZYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65Z
DAC60508ZYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65Z
DAC60508ZYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65Z
DAC60508ZYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	65Z
DAC70508MRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758M
DAC70508MRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758M
DAC70508MRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758M
DAC70508MRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758M
DAC70508MYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	75M
DAC70508MYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	75M
DAC70508MYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	75M
DAC70508MYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	75M
DAC70508ZRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758Z
DAC70508ZRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758Z
DAC70508ZRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758Z
DAC70508ZRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758Z
DAC70508ZRTETG4	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758Z
DAC70508ZRTETG4.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	758Z
DAC70508ZYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	75Z
DAC70508ZYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	75Z
DAC70508ZYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	75Z
DAC70508ZYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	75Z
DAC80508MCRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858MC
DAC80508MCRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858MC

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DAC80508MCRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858MC
DAC80508MCRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858MC
DAC80508MCYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85MC
DAC80508MCYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85MC
DAC80508MCYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85MC
DAC80508MCYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85MC
DAC80508MRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858M
DAC80508MRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858M
DAC80508MRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858M
DAC80508MRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858M
DAC80508MRTETG4	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858M
DAC80508MRTETG4.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858M
DAC80508MYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85M
DAC80508MYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85M
DAC80508MYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85M
DAC80508MYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85M
DAC80508ZCRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858ZC
DAC80508ZCRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858ZC
DAC80508ZCRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858ZC
DAC80508ZCRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858ZC
DAC80508ZCYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85ZC
DAC80508ZCYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85ZC
DAC80508ZCYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85ZC
DAC80508ZCYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85ZC
DAC80508ZRTER	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858Z
DAC80508ZRTER.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858Z
DAC80508ZRTERG4	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858Z
DAC80508ZRTERG4.B	Active	Production	WQFN (RTE) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858Z
DAC80508ZRTET	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858Z
DAC80508ZRTET.B	Active	Production	WQFN (RTE) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	858Z
DAC80508ZYZFR	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85Z

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DAC80508ZYZFR.B	Active	Production	DSBGA (YZF) | 16	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85Z
DAC80508ZYZFT	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85Z
DAC80508ZYZFT.B	Active	Production	DSBGA (YZF) | 16	250 | SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 125	85Z

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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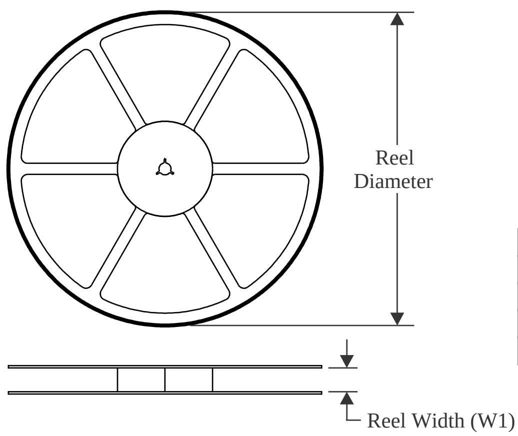
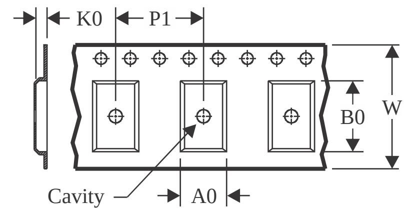
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

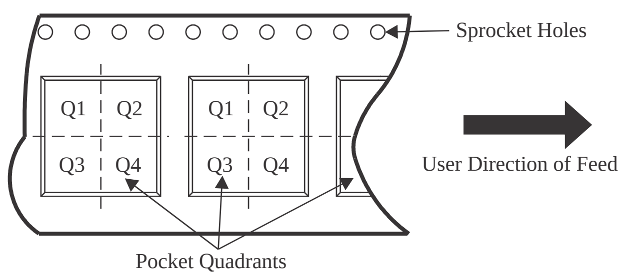


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

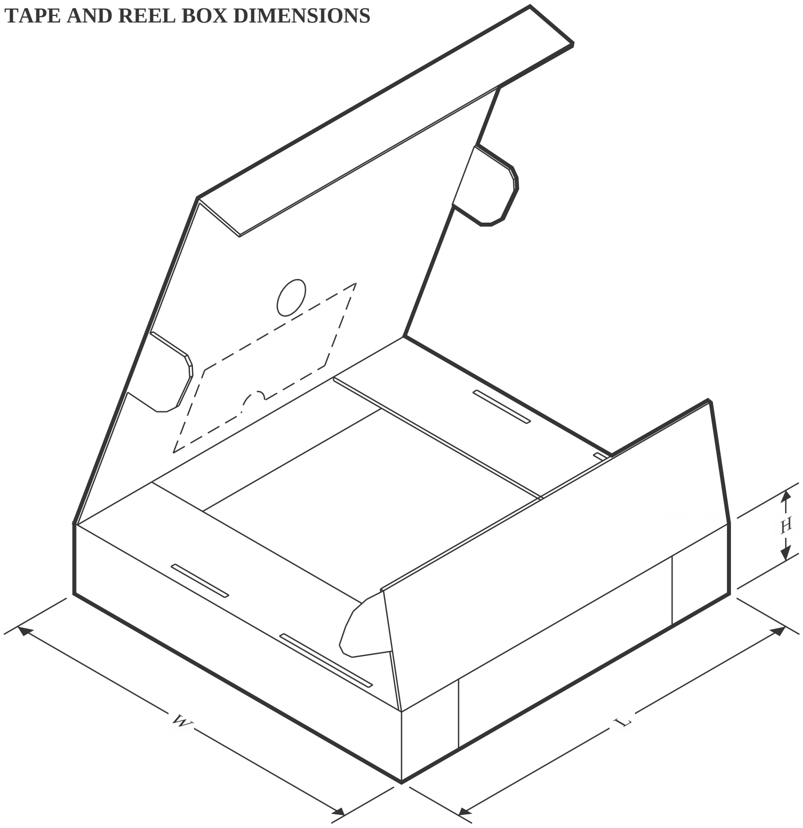


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DAC60508MCRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508MCRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508MCYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC60508MCYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC60508MRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508MRTERG4	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508MRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508MYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC60508MYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC60508ZCRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508ZCRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508ZCYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC60508ZCYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC60508ZRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508ZRTERG4	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC60508ZRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DAC60508ZYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC60508ZYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC70508MRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC70508MRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC70508MYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC70508MYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC70508ZRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC70508ZRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC70508ZRTETG4	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC70508ZYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC70508ZYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC80508MCRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508MCRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508MCYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC80508MCYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC80508MRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508MRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508MRTETG4	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508MYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC80508MYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC80508ZCRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508ZCRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508ZCYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC80508ZCYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC80508ZRTER	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508ZRTERG4	WQFN	RTE	16	3000	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508ZRTET	WQFN	RTE	16	250	180.0	12.4	3.3	3.3	1.0	8.0	12.0	Q2
DAC80508ZYZFR	DSBGA	YZF	16	3000	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1
DAC80508ZYZFT	DSBGA	YZF	16	250	180.0	8.4	2.54	2.54	0.76	4.0	8.0	Q1

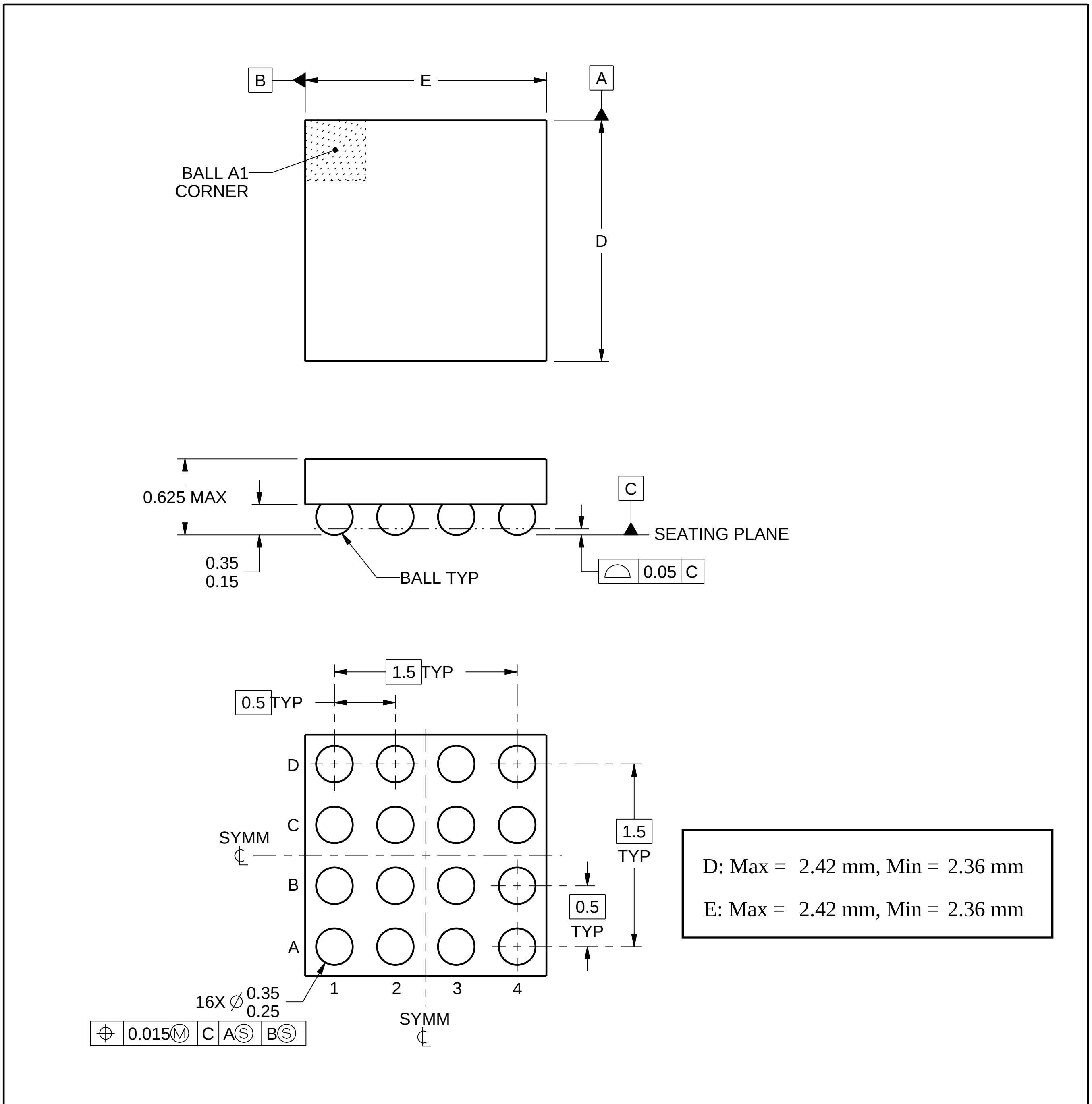
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DAC60508MCRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC60508MCRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC60508MCYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC60508MCYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0
DAC60508MRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC60508MRTERG4	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC60508MRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC60508MYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC60508MYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0
DAC60508ZCRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC60508ZCRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC60508ZCYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC60508ZCYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0
DAC60508ZRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC60508ZRTERG4	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC60508ZRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC60508ZYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC60508ZYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DAC70508MRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC70508MRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC70508MYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC70508MYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0
DAC70508ZRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC70508ZRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC70508ZRTETG4	WQFN	RTE	16	250	213.0	191.0	35.0
DAC70508ZYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC70508ZYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0
DAC80508MCRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC80508MCRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC80508MCYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC80508MCYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0
DAC80508MRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC80508MRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC80508MRTETG4	WQFN	RTE	16	250	213.0	191.0	35.0
DAC80508MYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC80508MYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0
DAC80508ZCRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC80508ZCRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC80508ZCYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC80508ZCYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0
DAC80508ZRTER	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC80508ZRTERG4	WQFN	RTE	16	3000	367.0	367.0	38.0
DAC80508ZRTET	WQFN	RTE	16	250	213.0	191.0	35.0
DAC80508ZYZFR	DSBGA	YZF	16	3000	182.0	182.0	20.0
DAC80508ZYZFT	DSBGA	YZF	16	250	182.0	182.0	20.0

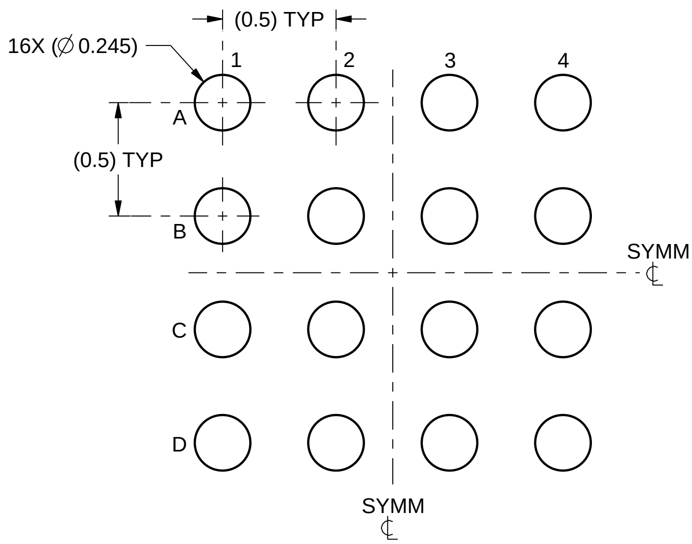


4222182/A 08/2015

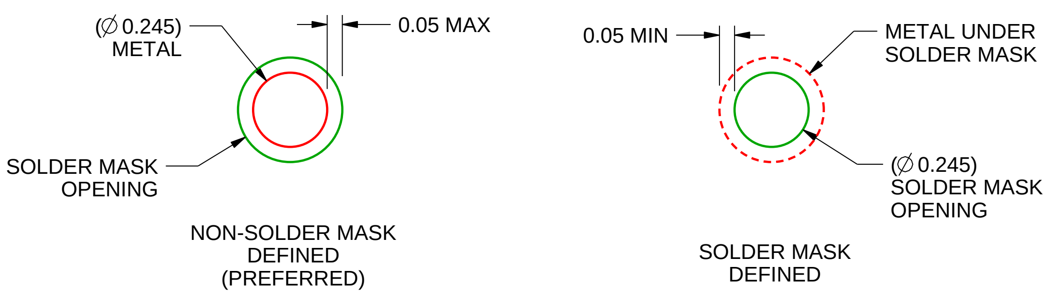
NanoFree Is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. NanoFree™ package configuration.



LAND PATTERN EXAMPLE
SCALE:30X



SOLDER MASK DETAILS
NOT TO SCALE

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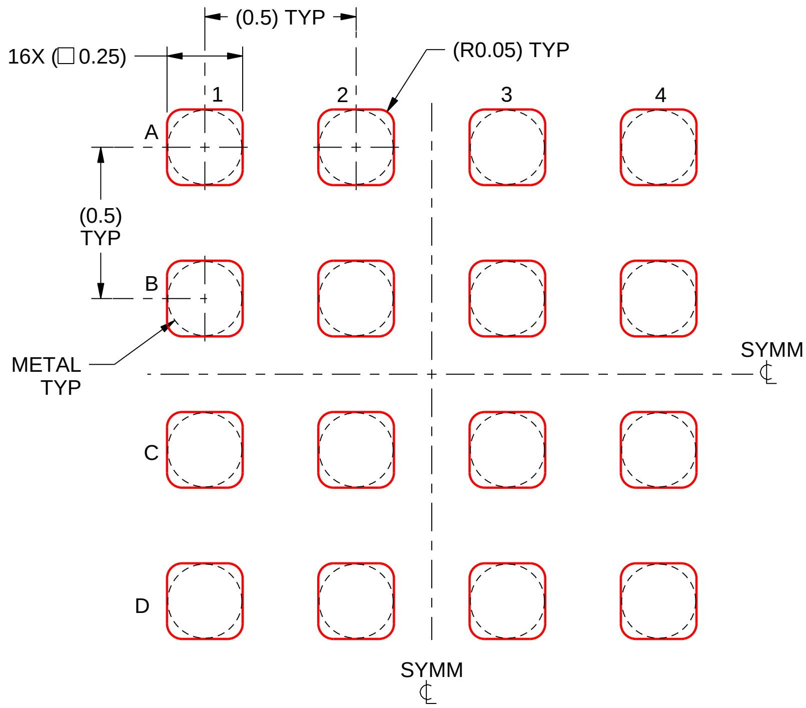
NOTES: (continued)

4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4222182/A 08/2015

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

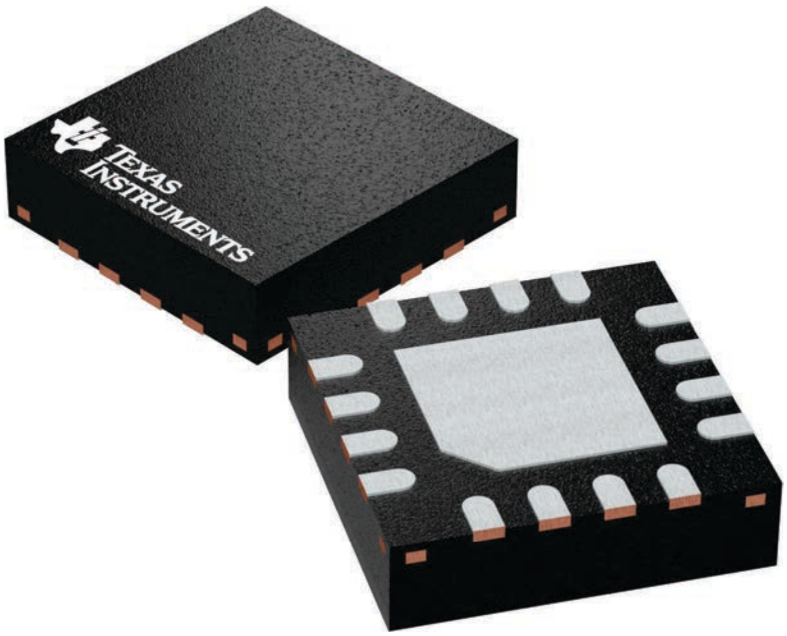
RTE 16

WQFN - 0.8 mm max height

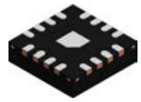
3 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



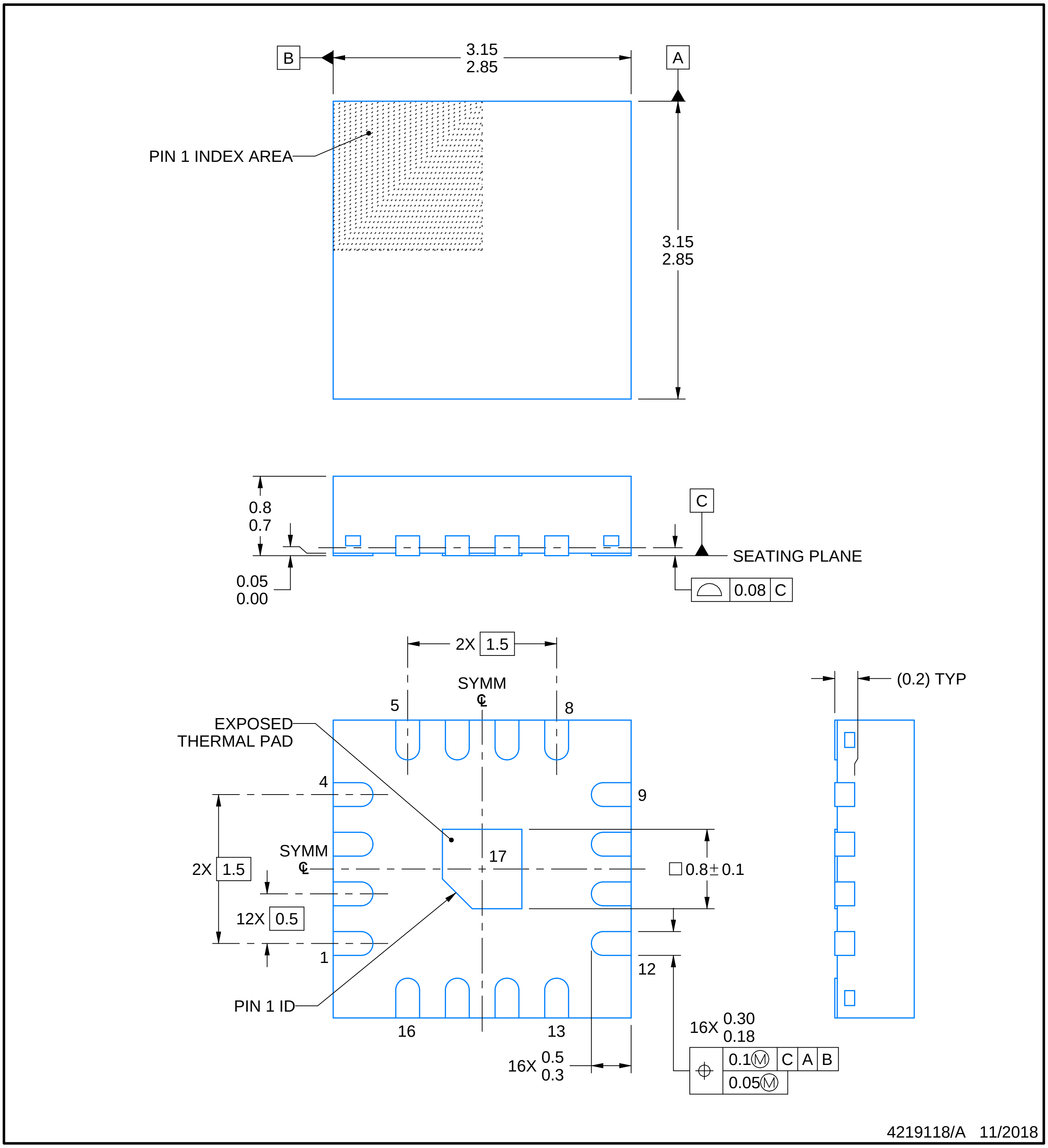
4225944/A



PACKAGE OUTLINE

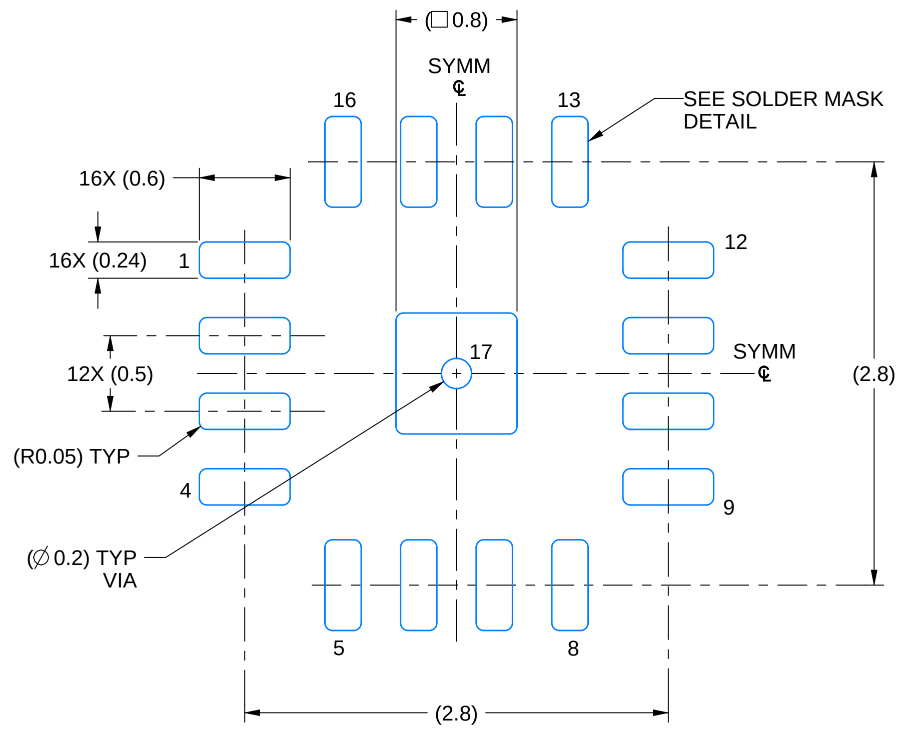
WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

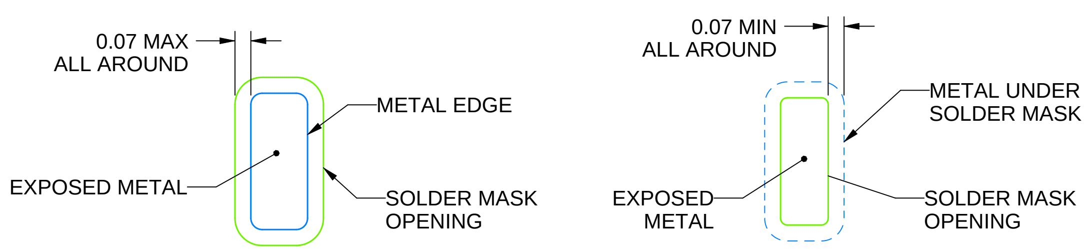


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



NON SOLDER MASK
DEFINED
(PREFERRED)

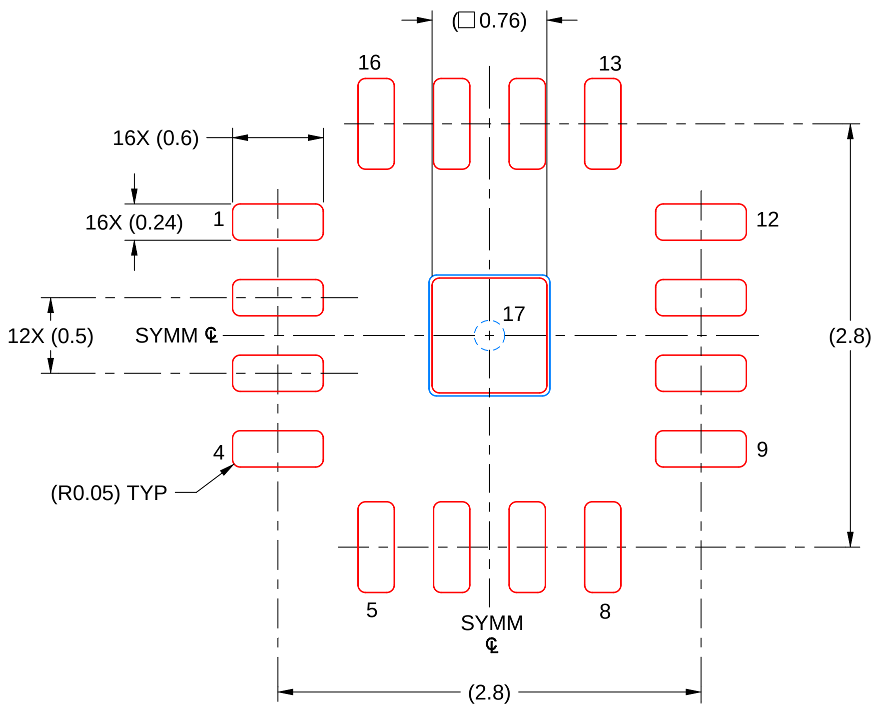
SOLDER MASK DEFINED

SOLDER MASK DETAILS

4219118/A 11/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 17
90% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4219118/A 11/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

重要なお知らせと免責事項

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